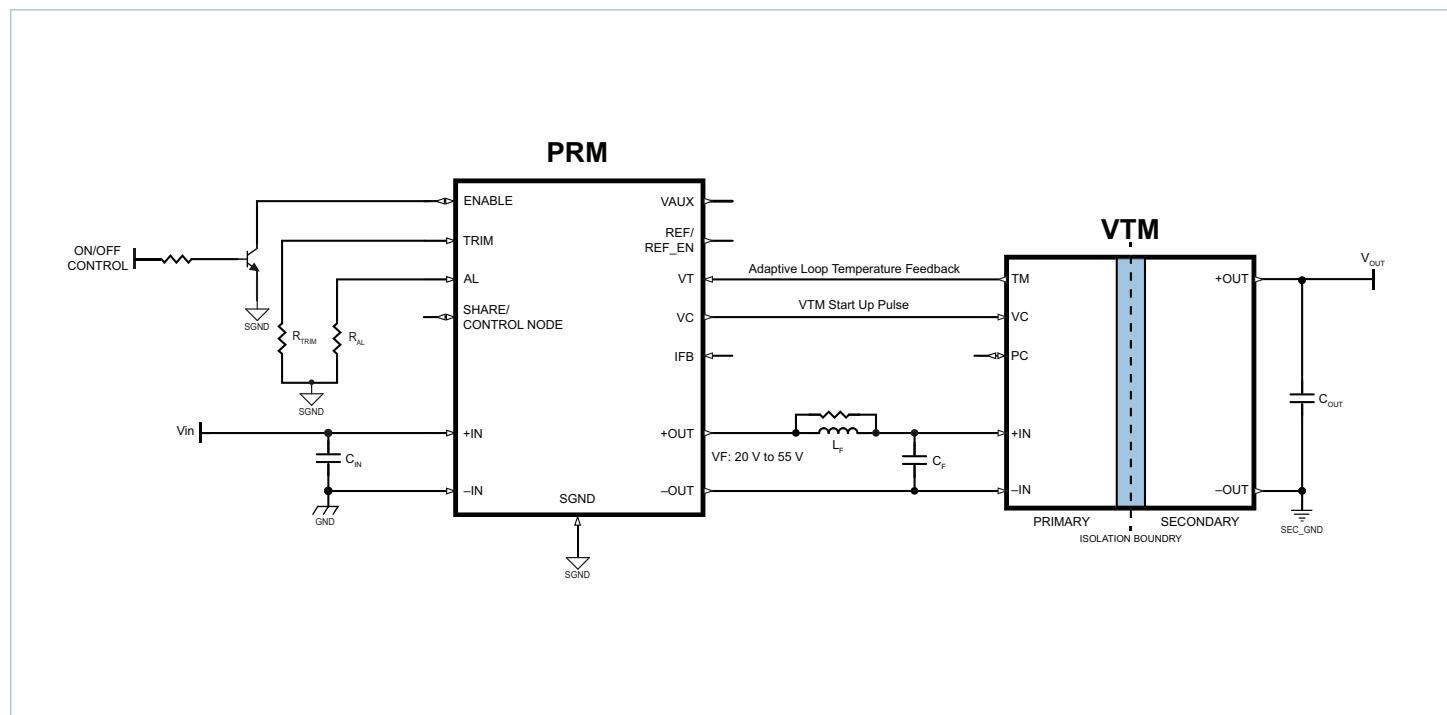
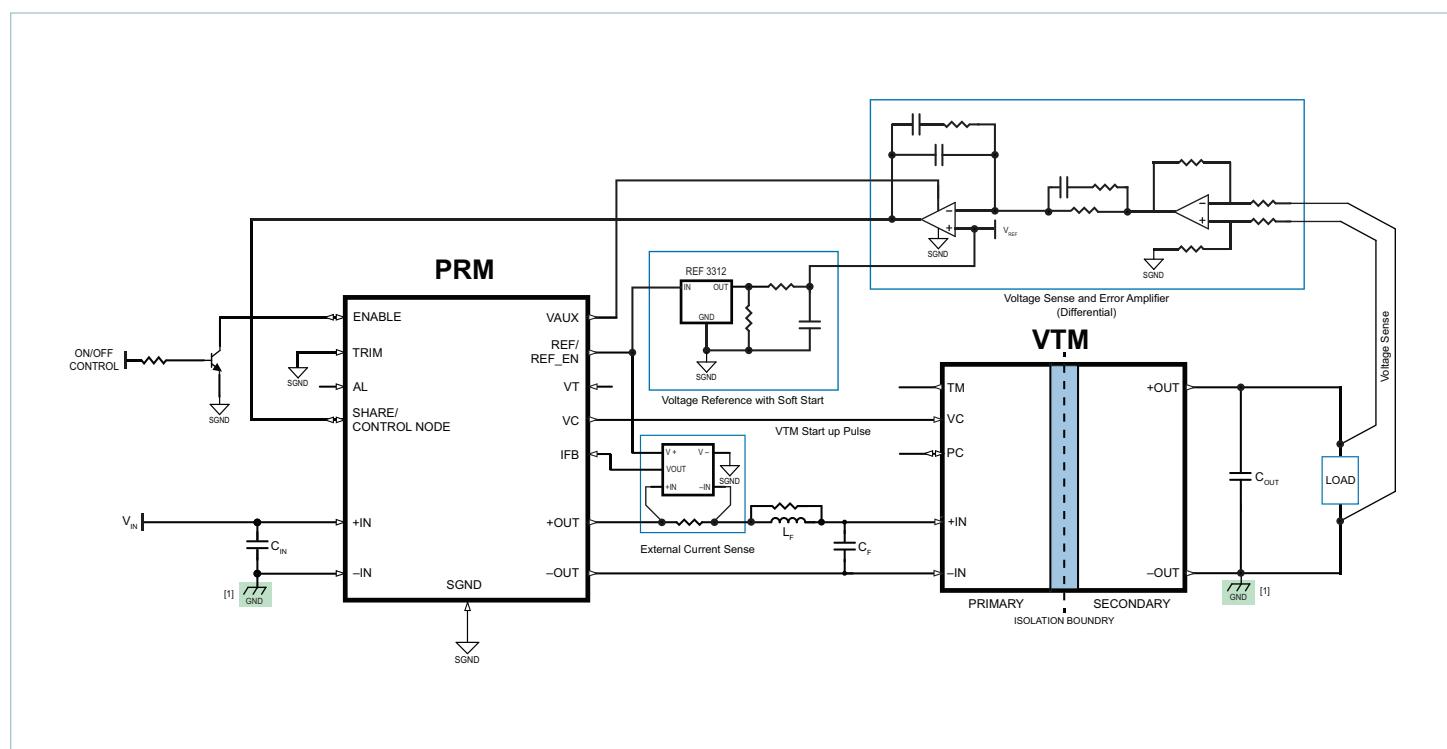




## Typical Applications



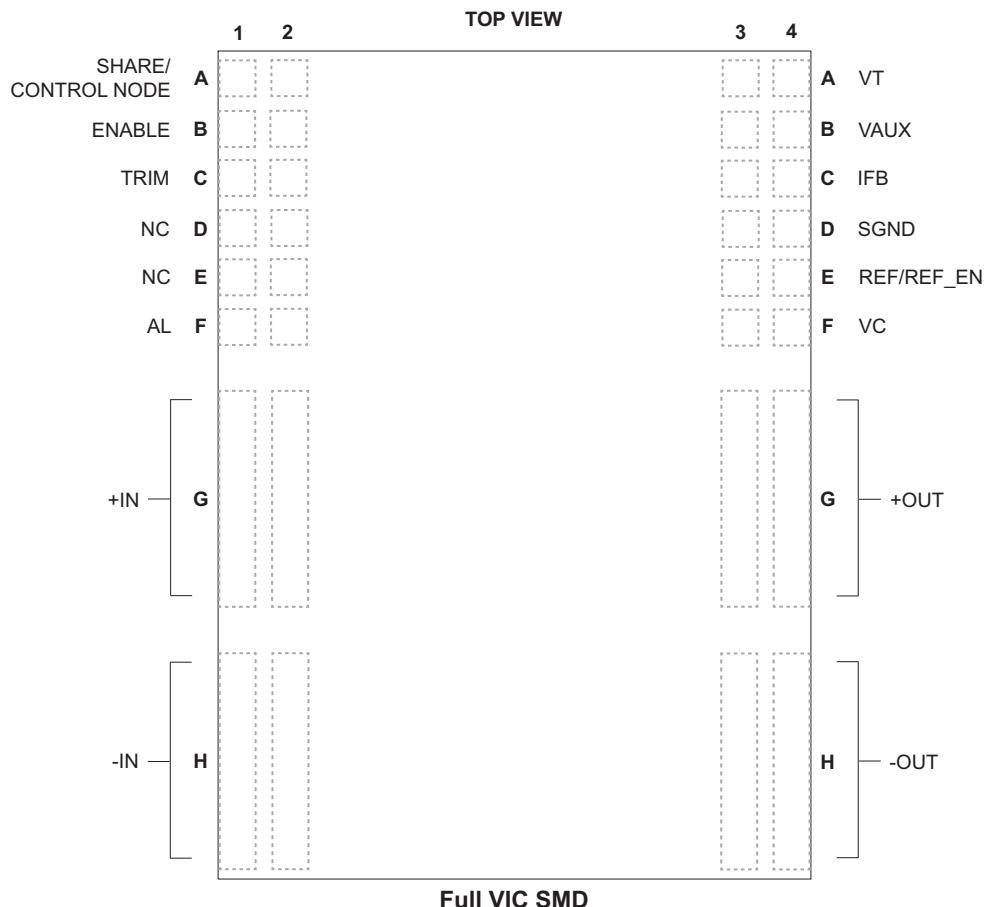
Typical Application: PRM48By480x500A00 + VTM Adaptive Loop Configuration



Typical Application: PRM48By480x500A00 + VTM, non-isolated Remote Sense Configuration

[1] Non-Isolated Configuration:  $-Out$  connected to  $-IN$

## Pin Configuration



## Pin Descriptions

Pin Number	Signal Name	Type	Function
A1, A2	SHARE (Adaptive Loop / Child Operation)	BIDIR	Parallel sharing control bus for parent-child configuration.
	CONTROL NODE (Remote Sense Operation)	INPUT	Modulator control node input. Driven by external error amplifier in Remote Sense Operation.
A3, A4	VT (Adaptive Loop Operation)	INPUT	VTM TM input for temperature compensation. Leave disconnected for Remote Sense Operation.
B1, B2	ENABLE	BIDIR	Enables power supply when allowed to float high. 5 V during normal operation.
B3, B4	VAUX	OUTPUT	9 V auxiliary bias voltage.
C1, C2	TRIM	INPUT	Selects operating mode. Adjusts output voltage in Adaptive Loop Operation.
C3, C4	IFB (Remote Sense Operation)	INPUT	Current sense input for current limit and overcurrent protection in Remote Sense Operation. Leave disconnected for Adaptive Loop Operation.
D1, D2	NC	n/a	Do not connect this pin.
D3, D4	SGND	INPUT	Signal ground, reference for analog controls. Kelvin connected internally to -IN and -OUT.
E1, E2	NC	n/a	Do not connect this pin.
E3, E4	REF (Adaptive Loop Operation)	OUTPUT	Reference voltage for internal error amplifier in Adaptive Loop Operation.
	REF_EN (Remote Sense Operation)	OUTPUT	Powers and enables external control circuit voltage reference in Remote Sense Operation.
F1, F2	AL (Adaptive Loop Operation)	INPUT	Adaptive loop gain control. Sets the magnitude of the Adaptive Loop load line in Adaptive Loop Operation. Leave disconnected for Remote Sense Operation.
F3, F4	VC	OUTPUT	Bias voltage to power VTM module during start up
G1, G2	+IN	INPUT POWER	Positive input power terminal
G3, G4	+OUT	OUTPUT POWER	Positive output power terminal
H1, H2	-IN	INPUT POWER RETURN	Negative input power terminal. Connected internally to -OUT.
H3, H4	-OUT	OUTPUT POWER RETURN	Negative output power terminal. Connected internally to -IN.















## Signal Specifications (cont.)

Specifications apply over all line and load conditions,  $T_{INT} = 25^\circ\text{C}$  and output voltage from 20.0 V to 55.0 V, unless otherwise noted.

**Boldface** specifications apply over the temperature range  $-40^\circ\text{C} < T_{INT} < 125^\circ\text{C}$  (T-grade).

TRIM (Adaptive Loop Operation Only)								
Signal Type	State	Attribute	Symbol	Conditions / Notes	Min	Typ	Max	Unit
Analog Input	Start up	Trim Enable Threshold	$V_{\text{TRIM\_EN}}$	Pull <b>below</b> this value during start up to enable trim control	<b>3.10</b>			V
		Trim Disable Threshold	$V_{\text{TRIM\_DIS}}$	Pull <b>above</b> this value during start up to disable trim control			<b>3.20</b>	V
		Minimum Trim Disable Resistance	$R_{\text{TRIM\_DIS\_MIN}}$	Minimum TRIM resistance required to disable trim	<b>10</b>			$\text{M}\Omega$
		Trim Capacitance (External)	$C_{\text{TRIM\_EXT}}$				<b>100</b>	pF
		Trim Sample Delay	$t_{\text{ENABLE\_TRIM}}$	From ENABLE high to TRIM sampled	<b>100</b>	140	<b>200</b>	$\mu\text{s}$
	Normal Operation	TRIM Pin Analog Range	$V_{\text{TRIM\_RANGE}}$	See Figure 26	<b>1.00</b>		<b>2.75</b>	V
		TRIM Gain	$G_{\text{TRIM}}$	$V_{\text{OUT}} / V_{\text{TRIM}}, V_{\text{TRIM}}$ applied within active range		20		V / V
		Trim Accuracy	$\%_{\text{ACC\_TRIM}}$	Vout accuracy, exclusive of external resistor tolerance		0.5	<b>2.0</b>	%
		$V_{\text{OUT}}$ Referred Trim Resolution	$V_{\text{OUT\_RES}}$			200		mV
		Trim Latency	$t_{\text{TRIM\_LAT}}$		<b>60</b>	120	<b>240</b>	$\mu\text{s}$
		Trim Bandwidth	$\text{BW}_{\text{TRIM}}$	-3dB point		1.2		kHz

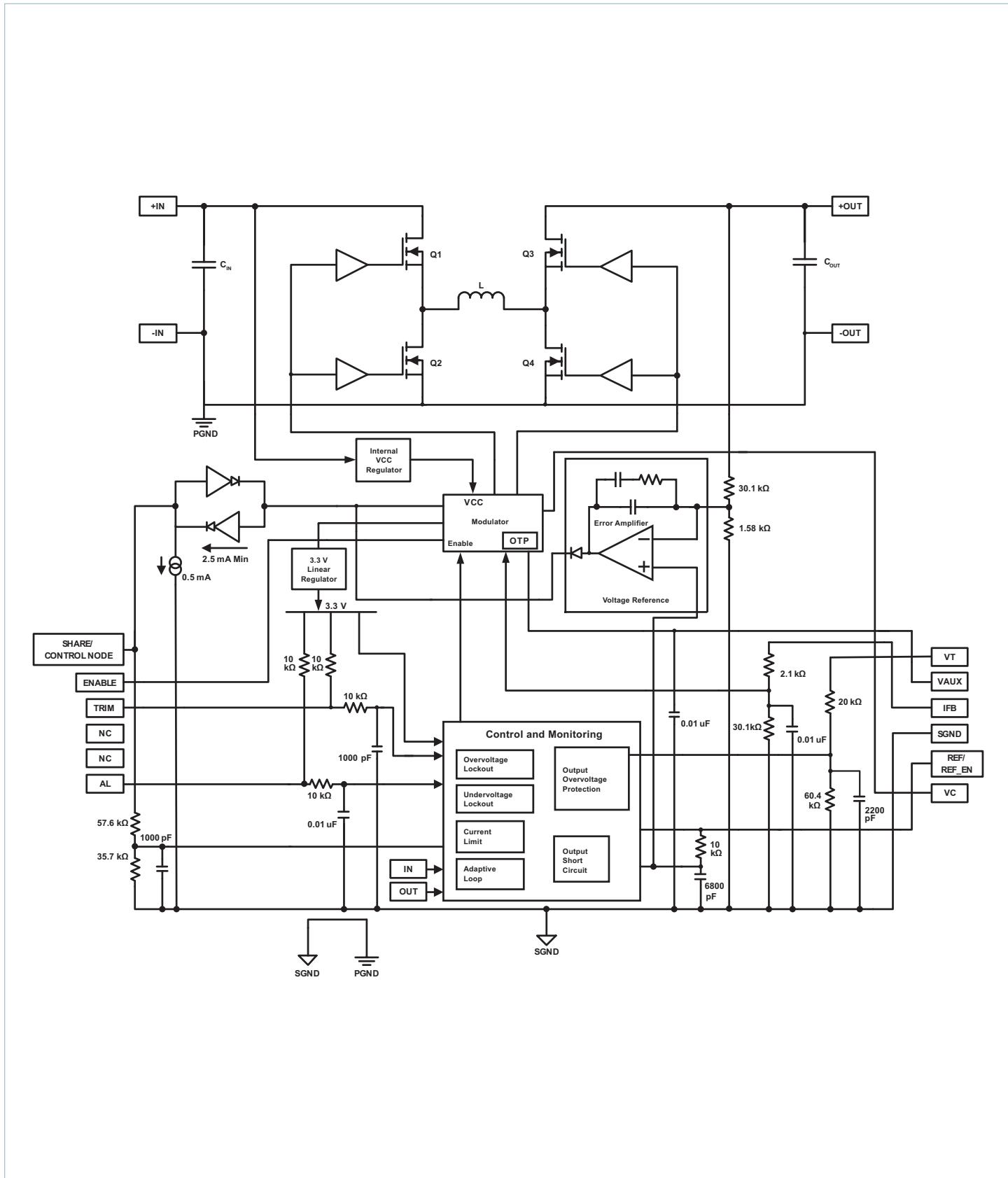






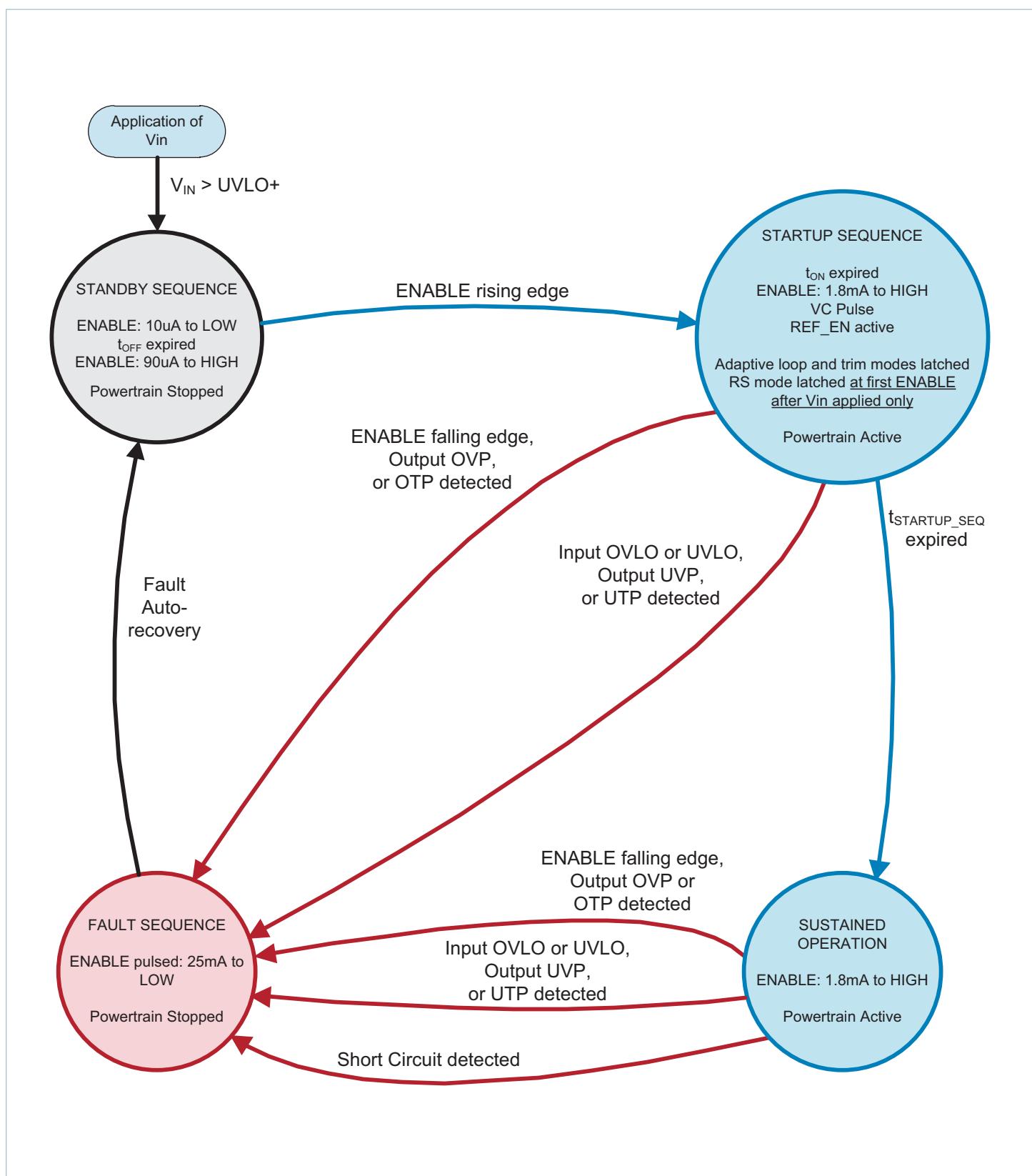


## Functional Block Diagram



## High Level Functional State Diagram

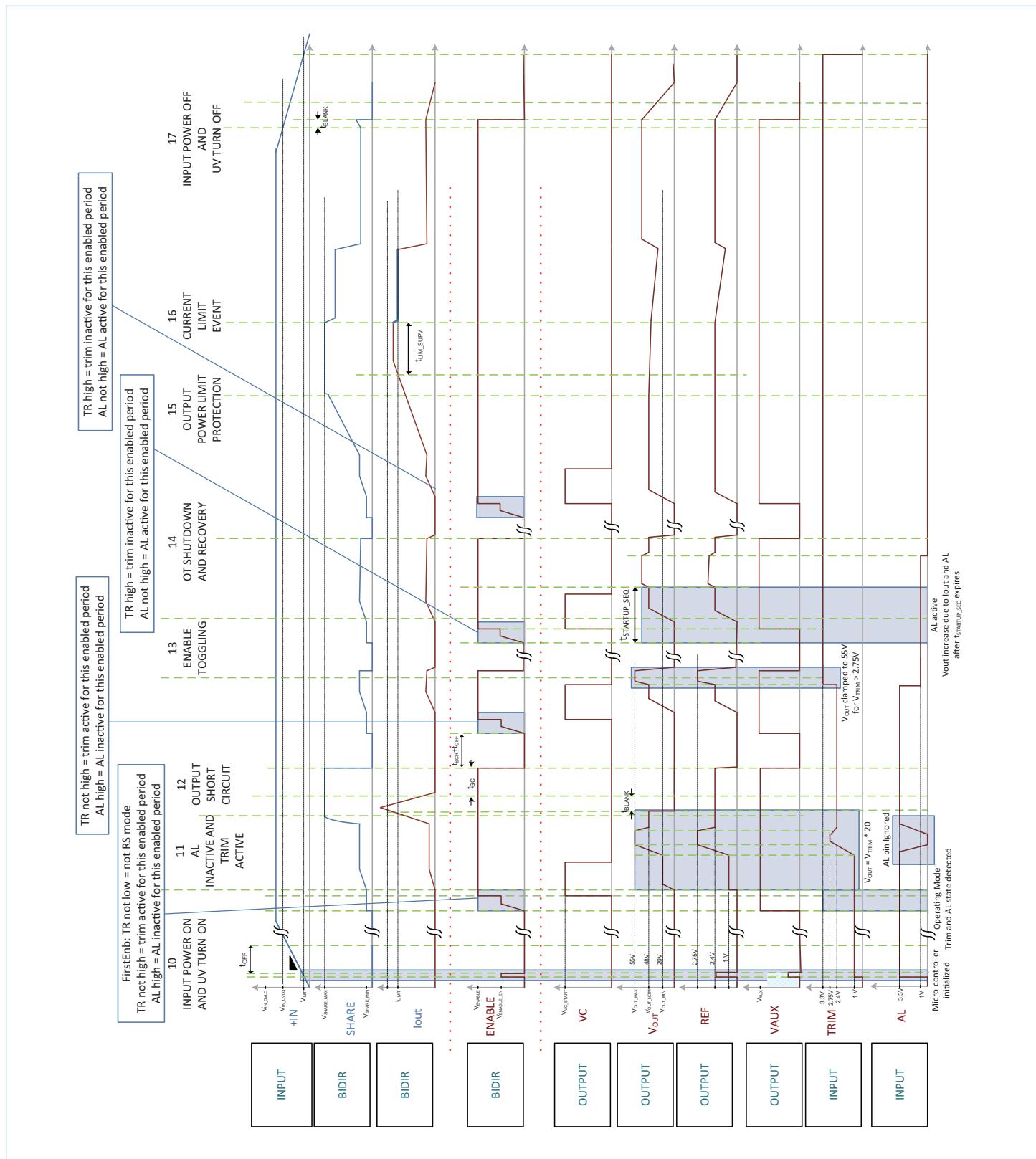
Conditions that cause state transitions are shown along arrows. Sub-sequence activities listed inside the state bubbles.





## Timing Diagrams (Adaptive Loop Operation) (cont.)

Module Inputs are shown in blue; Module Outputs are shown in brown.











## Typical Performance Characteristics (cont.)

The following figures present typical performance at  $T_C = 25^\circ\text{C}$ , unless otherwise noted. See associated figures for general trend data.

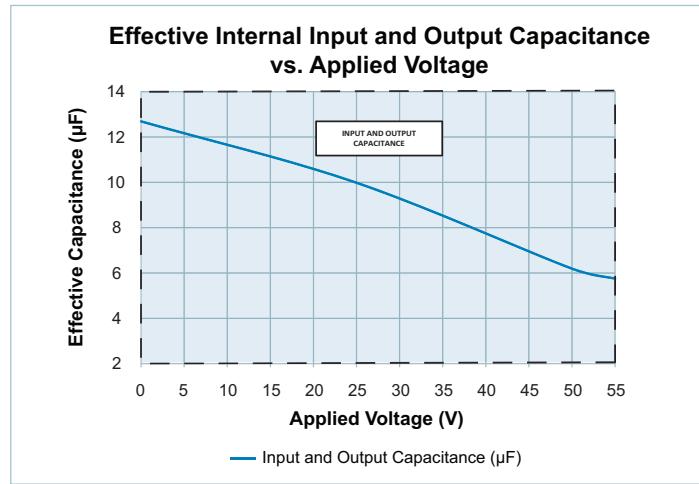


Figure 13 — Effective Internal Input and Output Capacitance vs. Voltage – Ceramic Type

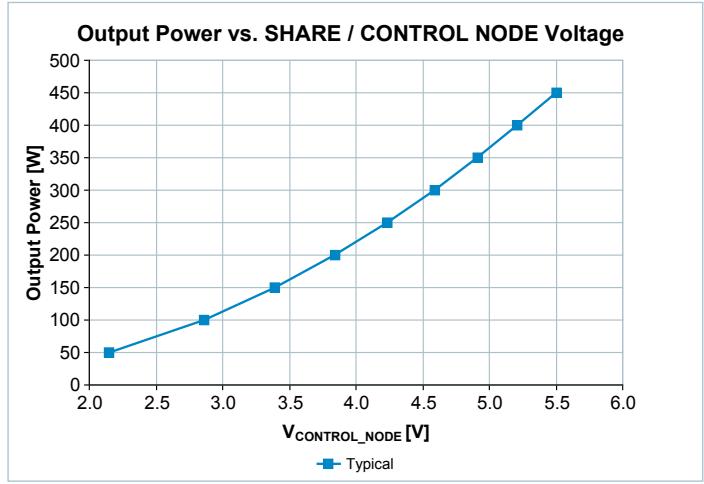


Figure 16 — Output Power vs. SHARE / CONTROL NODE Voltage;  $V_{IN} = 48.0 \text{ V}$ ,  $V_{OUT} = 48.0 \text{ V}$ ,  $T_{CASE} = 25^\circ\text{C}$

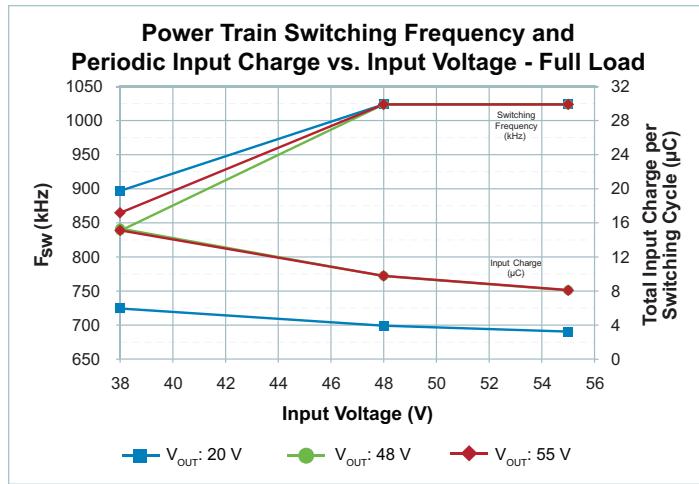


Figure 14 — Typical Power Train Switching Frequency and Periodic Input Charge vs.  $V_{IN}$ ,  $V_{OUT}$ ,  $I_{OUT} = 10.42 \text{ A}$

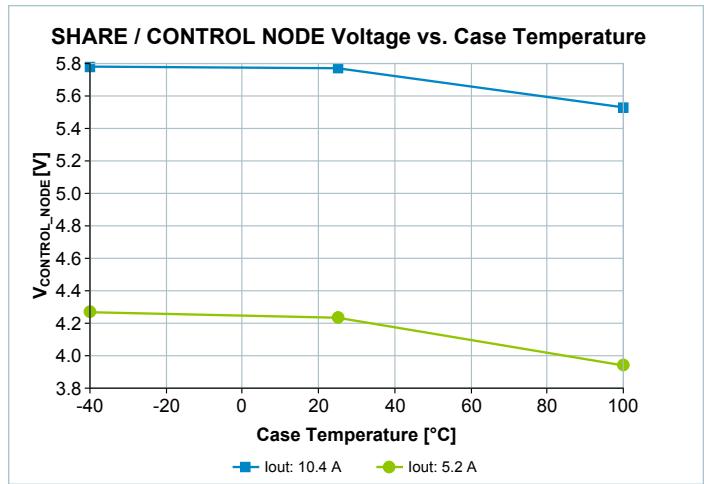


Figure 17 — Typical SHARE / CONTROL NODE Voltage vs.  $T_{CASE}$  and  $I_{OUT}$ ;  $V_{IN} = 48.0 \text{ V}$ ,  $V_{OUT} = 48.0 \text{ V}$

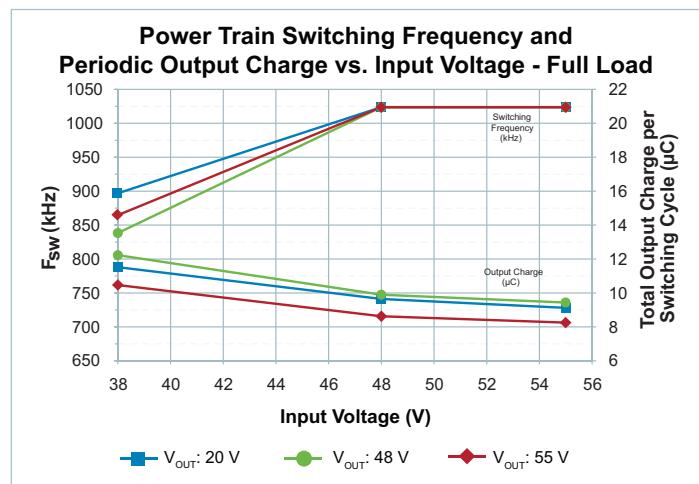


Figure 15 — Typical Power Train Switching Frequency and Periodic Output Charge vs.  $V_{IN}$ ,  $V_{OUT}$ ,  $I_{OUT} = 10.42 \text{ A}$

## Typical Performance Characteristics (cont.)

The following figures present typical performance at  $T_C = 25^\circ\text{C}$ , unless otherwise noted. See associated figures for general trend data.

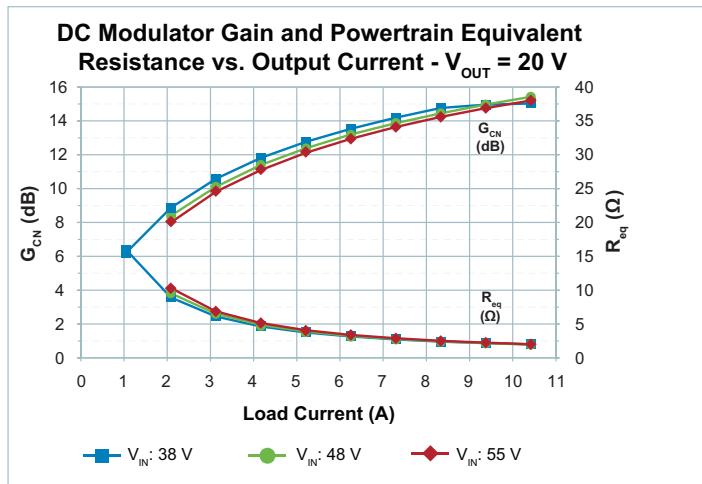


Figure 18 — Powertrain Characteristics vs.  $I_{\text{OUT}}$ ;  $V_{\text{IN}}$  Resistive Load,  $V_{\text{OUT}} = 20.0 \text{ V}$

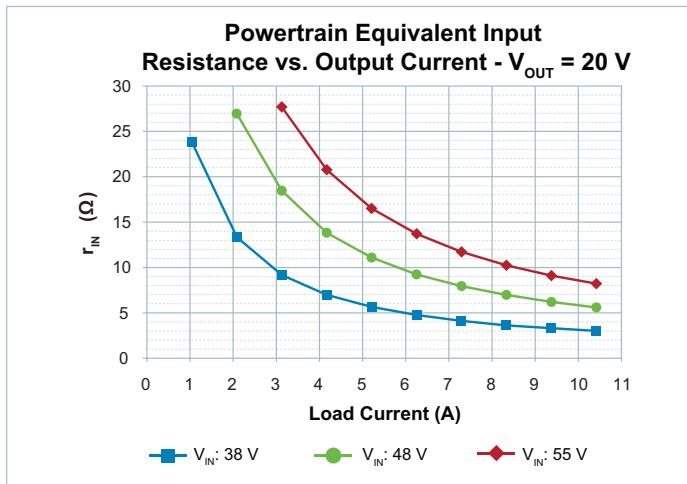


Figure 21 — Magnitude of powertrain dynamic input impedance vs.  $I_{\text{OUT}}$ ;  $V_{\text{IN}}$ ;  $V_{\text{OUT}} = 20.0 \text{ V}$

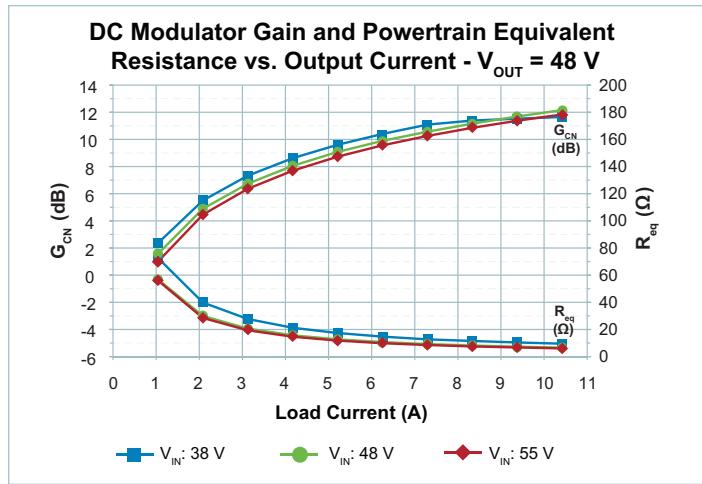


Figure 19 — Powertrain Characteristics vs.  $I_{\text{OUT}}$ ;  $V_{\text{IN}}$  Resistive Load,  $V_{\text{OUT}} = 48.0 \text{ V}$

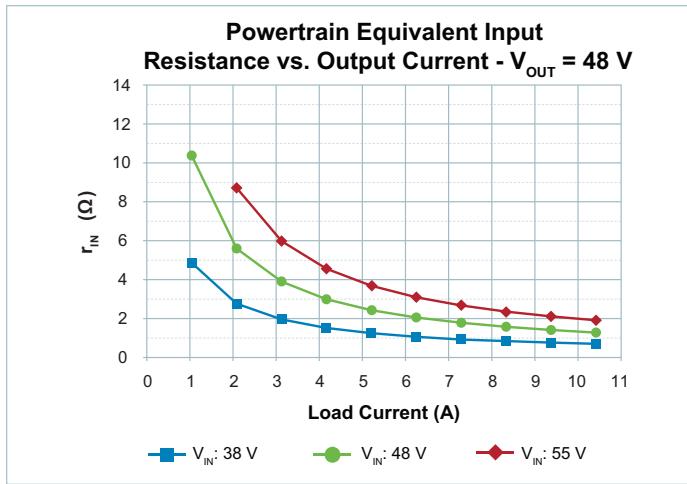


Figure 22 — Magnitude of powertrain dynamic input impedance vs.  $I_{\text{OUT}}$ ;  $V_{\text{IN}}$ ;  $V_{\text{OUT}} = 48.0 \text{ V}$

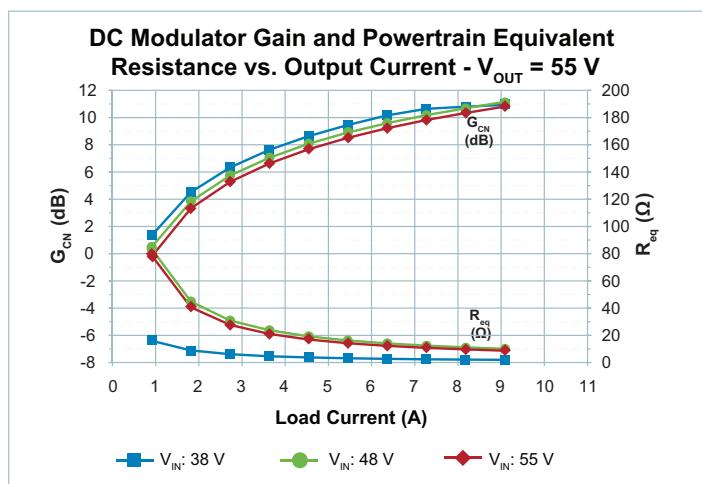


Figure 20 — Powertrain Characteristics vs.  $I_{\text{OUT}}$ ;  $V_{\text{IN}}$  Resistive Load,  $V_{\text{OUT}} = 55.0 \text{ V}$

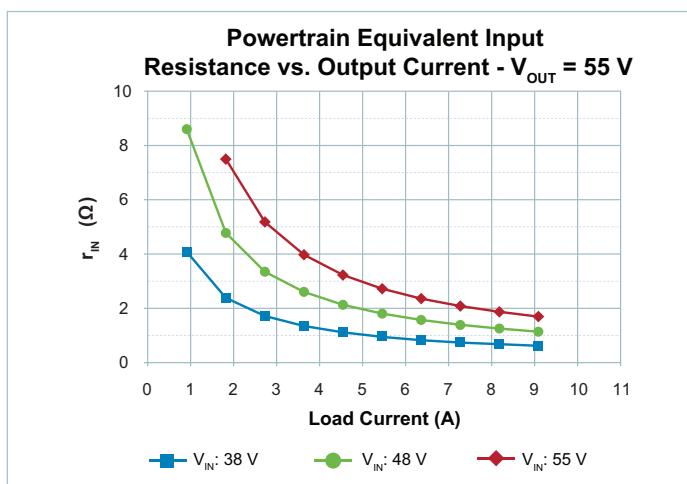


Figure 23 — Magnitude of powertrain dynamic input impedance vs.  $I_{\text{OUT}}$ ;  $V_{\text{IN}}$ ;  $V_{\text{OUT}} = 55.0 \text{ V}$

## General Characteristics

Specifications apply over all line and load conditions,  $T_{INT} = 25^\circ\text{C}$  and output voltage from 20.0 V to 55.0 V, unless otherwise noted.  
**Boldface specifications apply over the temperature range of  $-40^\circ\text{C} < T_{INT} < 125^\circ\text{C}$  (T-grade).**

Attribute	Symbol	Conditions / Notes	Min	Typ	Max	Unit
<b>Mechanical</b>						
Length	L		<b>32.3</b>	<b>32.5</b>	<b>32.8</b>	mm
			(1.27)	(1.28)	(1.29)	in
Width	W		<b>21.8</b>	<b>22.0</b>	<b>22.3</b>	mm
			(0.86)	(0.87)	(0.88)	in
Height	H		<b>6.48</b>	<b>6.73</b>	<b>6.98</b>	mm
			(0.255)	(0.265)	(0.275)	in
Volume	Vol	No Heatsink		<b>4.81</b>		cm <sup>3</sup>
				(0.30)		in <sup>3</sup>
Weight	W			<b>15</b>		g
Lead Finish		Nickel	<b>0.51</b>		<b>2.03</b>	μm
		Palladium	<b>0.02</b>		<b>0.15</b>	
		Gold	<b>0.003</b>		<b>0.050</b>	
<b>Thermal</b>						
Operating Internal Temperature	$T_{INT}$	T Grade	<b>-40</b>		<b>125</b>	°C
		M Grade	<b>-55</b>		<b>125</b>	°C
Thermal Impedance	$\theta_{INT-CASE}$			<b>1</b>		°C/W
	$\theta_{INT-LEAD}$			<b>3</b>		°C/W
Thermal Capacity				<b>10</b>		Ws / °C
<b>Assembly</b>						
Peak Compressive Force Applied to Case (Z-axis)		Supported by J-Lead only			<b>6</b>	lbs
					<b>5.4</b>	lbs / in <sup>2</sup>
Storage Temperature	$T_{ST}$	T Grade	<b>-40</b>		<b>125</b>	°C
		M Grade	<b>-65</b>		<b>125</b>	°C
ESD Rating	HBM	Method per Human Body Model Test ESDA/JEDEC JDS-001-2012		<b>CLASS 1C</b>		V
				<b>CLASS 2</b>		
<b>Soldering</b>						
Peak Temperature During Reflow		MSL 4 (Datecode 1528 and later)			<b>245</b>	°C
Maximum Time Above 217 °C				<b>60</b>	<b>90</b>	s
Peak Heating Rate During Reflow				<b>1.5</b>	<b>2.0</b>	°C / s
Peak Cooling Rate Post Reflow				<b>2.5</b>	<b>3.0</b>	°C / s
<b>Reliability and General Agency Approvals</b>						
MTBF		Telcordia Issue 2 - Method I Case 1; Ground Benign, Controlled		<b>5.28</b>		MHrs
		MIL-HDBK-217 Plus Parts Count - 25C Ground Benign, Stationary, Indoors / Computer Profile		<b>4.01</b>		MHrs
Agency Approvals / Standards		cTUV <sub>US</sub>				
		CE Marked for Low Voltage Directive and RoHS Recast Directive, as applicable				

## Pin Functions

### +IN, -IN

Input power pins

### +OUT, -OUT

Output power pins. Module cannot sink current.

### ENABLE

This pin turns the supply on and off. The pin is both an input and an output and can provide the following features:

- Delayed Start: upon application of voltage (>UVLO) to the module power input and after  $t_{off}$ , the ENABLE pin will source a constant 90  $\mu$ A current.
- Output enable: When ENABLE is allowed to pull up above the enable threshold, the ENABLE pin will pull up to 5 V with 1.8 mA source capability, and the module will be enabled.
- Output disable: ENABLE may be pulled down externally in order to disable the module. Pull down resistance should be less than 235  $\Omega$  to SGND.
- Fault detection flag: The ENABLE 5 V voltage source is internally turned off when a fault condition is detected.

ENABLE control should be implemented using an open collector configuration. It is not recommended to drive this pin externally.

### V AUX: Auxiliary Voltage Source

Use this pin to power external devices with a non-isolated 9 V supply, with up to 5 mA load capability, switched with ENABLE input. Do not place a capacitor over 0.04  $\mu$ F on this pin.

### SGND: Signal Ground

This is a low current pin which provides a Kelvin connection to the PRMs internal signal ground. Use this pin as the ground reference for external circuitry and signals to avoid voltage drops caused by high currents on power returns. In array configurations, SGND pins should be star connected at a single point. A series resistor (~1 $\Omega$ ) to the star location is recommended to decouple return currents.

### VC: VTM Control

This output pin is used to temporarily provide VCC voltage to connected VTMs during start up. The pulse is nominally 14 V, 10 ms wide. A VTM can self-power once its input voltage reaches its minimum specified input voltage. The PRM output must be checked to make sure it reaches this threshold voltage before the VC pulse expires.

### TRIM

The TRIM pin is used to select the operating mode and to trim the PRM output when Adaptive Loop operating mode is selected. The TRIM pin has an internal pull-up to V<sub>CC\_INT</sub> through a 10 k $\Omega$  resistor.

#### Operating Mode Select:

If TRIM is pulled below 0.45 V during the first startup after V<sub>IN</sub> is applied, Remote Sense / Child operation is selected.

Otherwise, Adaptive Loop operation is selected.

This selection persists until V<sub>IN</sub> is removed from the part, and is not changed by fault or disable events.

#### Output Voltage Trim:

Sets the output voltage of the PRM in Adaptive Loop operation.

If TRIM is permitted to pull up to 3.20 V or higher during start up, trim is disabled, and the output is set to the nominal of 48.0 V.

If TRIM is held between 1.00 V to 2.75 V during start up, trim is enabled, and the output is scaled by a factor of 20 resulting in an output voltage range of 20.0 V to 55.0 V.

This selection persists until the PRM is restarted with the ENABLE pin, or due to fault auto-recovery.

### AL: Adaptive Loop (Adaptive Loop Operation)

This input pin allows you to set the Adaptive Loop load line. Every volt on this pin represents 0.5  $\Omega$  of positive output slope. There is an internal 10 k $\Omega$  pullup resistor to V<sub>CC\_INT</sub>. If AL is permitted to pull up to 3.20 V or higher during start up, the Adaptive Loop load line is disabled.

This selection persists until the PRM is restarted with the ENABLE pin, or due to fault auto-recovery.

### VT: VTM Temperature (Adaptive Loop Operation)

This pin is used in the Adaptive Loop compensation algorithm to account for the VTM output resistance variation as a function of temperature. The VTM TM pin provides this voltage, scaled as the temperature in K (Kelvin) divided by 100, so 25°C is 2.98 V. Leave disconnected or pull below 1.9 V to disable. The adjustment is fixed at 0.3%/°C relative to the value at 25°C

### REF: Reference (Adaptive Loop Operation)

This output pin allows you to monitor the internal reference voltage in Adaptive Loop Operation. During normal operation it represents the output voltage scaled by a factor of 20.

In Adaptive Loop Operation this pin is for monitoring purposes only and should not be driven or loaded externally.

### REF\_EN: Reference Enable (Remote Sense Operation)

In Remote Sense Operation this pin outputs a regulated 3.25 V, 4 mA voltage source. It is enabled only after successful start up of the PRM powertrain. REF\_EN is intended to power the output current transducer and also the voltage reference for the external control loop. Powering the reference generator with REF\_EN helps provide a controlled start up, since the output voltage of the system is able to track the reference level as it comes up.

### SHARE (Adaptive Loop and Child Operation)

This bus sets the output current level for all the PRM modules when operating in an array (parent-child configuration). Connect them together among the modules in the shared bus. One PRM should be configured as a parent by connecting TRIM for Adaptive Loop Operation. All other PRMs should be configured as children by pulling their respective TRIM pins low. This pin can be used to monitor the error voltage externally. 0 to 100% load is represented by a voltage between 0.79 V and 7.40 V.

### CONTROL NODE (Remote Sense Operation)

In Remote Sense Operation, this is the input to the modulator which determines the powertrain timing and ultimately the module output power. An internal 0.5 mA current sink is always active. The bi-directional buffer between CONTROL NODE and the modulator has two states. In normal operation, CONTROL NODE will be above the 0.79 V switching threshold, and will drive the modulator through the buffer. An internal 7.40 V clamp determines the maximum output power that can be requested of the modulator.

When CONTROL NODE falls below 0.79 V, the converter will stop switching. An internal circuit clamps the modulator input to 7.40 V, and a buffer will source up to 2.5 mA out of the pin at that clamp level. For this reason, the output impedance of the amplifier driving CONTROL NODE must be taken into account. A rail-to-rail operational amplifier with low output impedance is always recommended.

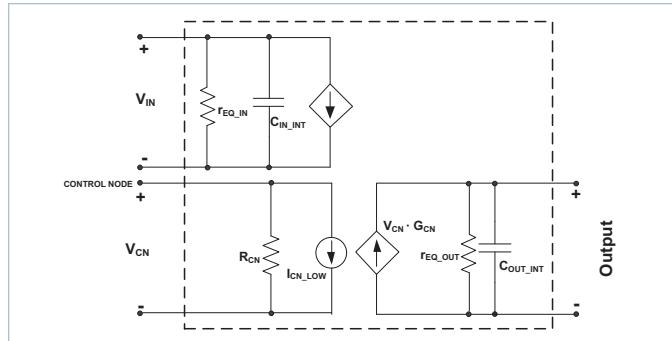


Figure 24 — PRM48By480x500A00 AC small signal model

The powertrain small signal (plant) response consists of a single pole determined by the load resistance, the powertrain equivalent output resistance, and the total output capacitance (internal and external to the module). Both the modulator gain and the equivalent output resistance vary as a function of line, load and output voltage. As the load increases, the powertrain pole moves to higher frequency. As a result, the closed loop crossover frequency will be the highest at full load and lowest at minimum load. Figure 24 shows a reference AC small-signal model.

#### IFB: Current Feedback (Remote Sense Operation)

In Remote Sense Operation, IFB is the input for the module output overcurrent protection and current limit features. A voltage proportional to the powertrain output current must be applied to IFB in order for overcurrent protection to operate properly.

If the IFB voltage exceeds the IFB pin's overcurrent protection threshold, the powertrain will stop switching. If the IFB voltage falls below the overcurrent protection threshold within  $t_{BLANK}$  time, then the powertrain will immediately resume switching. Otherwise a fault is detected.

The current limit threshold for the IFB pin is set lower than the protection threshold. When the IFB pin average voltage exceeds the current limit threshold, an internal integrator will activate a clamp amplifier which overrides the modulator input maximum level. This causes the powertrain to maintain a constant output current. The bandwidth of this current limit integrator is significantly slower than that of the CONTROL NODE input. Therefore this current limit cannot be used in lieu of properly compensating the (external) control loop to avoid exceeding maximum current or power ratings for the device.

## Design Guidelines

The PRM48By480x500A00 regulator is specifically designed to provide a controlled Factorized Bus distribution voltage for powering downstream VTM Transformer — fast, efficient, isolated, low noise Point-of-Load (POL) converters.

The PRM48By480x500A00 can be configured for two operating modes depending on the type of regulation required.

In Adaptive Loop Operation the regulation circuitry is enabled within the device and regulates the voltage at the output terminals. The PRM48By480x500A00 has a programmable Adaptive Loop load line which can be used to compensate for downstream VTM output resistance allowing for precise point of load regulation without the need for remote sensing.

In Remote Sense Operation, the internal regulation circuitry is disabled and the voltage regulation circuitry is provided externally allowing for remote sensing directly at the point of load. In certain applications Remote Sense Operation can improve regulation accuracy, and allow for operating with high amounts of load capacitance and optimizing load transient response.

#### Operating Mode Selection

The operating mode is selected through use of the TRIM pin. When the part is first enabled after  $V_{IN}$  is applied, the TRIM voltage is sampled. The TRIM pin has an internal pull up resistor to  $V_{CC\_INT}$ , so unless external circuitry pulls the pin voltage lower, it will float up to  $V_{CC\_INT}$ .

If TRIM is pulled lower than 0.45 V during the first startup after  $V_{IN}$  is applied, the part will be configured for Remote Sense / Child Operation, where the internal voltage regulation circuitry is disabled. In this case, for all subsequent operation the part will output a voltage dependent on the SHARE / CONTROL NODE voltage provided externally (either from an external regulation circuit or parent PRM).

To configure the part for Remote Sense or Child Operation, connect the TRIM pin to SGND. It is recommended to make this connection through a  $0\ \Omega$  jumper for troubleshooting purposes.

If the sampled TRIM voltage is higher than 0.55 V during the first startup after  $V_{IN}$  is applied, then the part will be configured for Adaptive Loop Operation, and the internal voltage regulation circuitry is enabled. The PRM will output a voltage dependent on the TRIM voltage, and will remain in this mode for as long as  $V_{IN}$  is applied.

To configure the part for Adaptive Loop Operation, leave the TRIM pin disconnected, or apply a voltage/resistance within the specified range.

The operating mode is detected during the first start up after  $V_{IN}$  is applied. This selection persists until  $V_{IN}$  is removed from the part, and is not changed by fault or disable events. Changing the operating mode can only be done by removing  $V_{IN}$ .

## Design Guidelines (Adaptive Loop Operation)

In Adaptive Loop Operation, the internal voltage control circuitry is enabled and the voltage at the output terminals is regulated. The part is nominally set to provide a fixed 48.0 V output, and the TRIM pin can be used to adjust the output over the range of 20.0 V to 55.0 V.

When used with a VTM, the AL pin provides ability to program an Adaptive Loop load line to compensate for the output resistance ( $R_{OUT}$ ) of a downstream VTM, while the VT pin provides temperature compensation to account for changes in the VTM  $R_{OUT}$  over temperature.

### Trim Mode and Output Trim Control (Adaptive Loop Operation)

In Adaptive Loop Operation, during any start up and after ENABLE transitions high, the TRIM pin voltage is sampled to determine if trim is active or inactive. If the sampled TRIM voltage is higher than 3.20 V then the PRM will disable trim. In this case, for all subsequent operation the output voltage will be programmed to the nominal output of 48.0 V and the TRIM pin will be ignored during normal operation.

If the sampled TRIM voltage is between 1.00 V and 2.75 V then the PRM will activate trim mode and it will remain in this mode as long as the PRM is operating.

This selection persists until the PRM is restarted with the ENABLE pin, or due to fault auto-recovery.

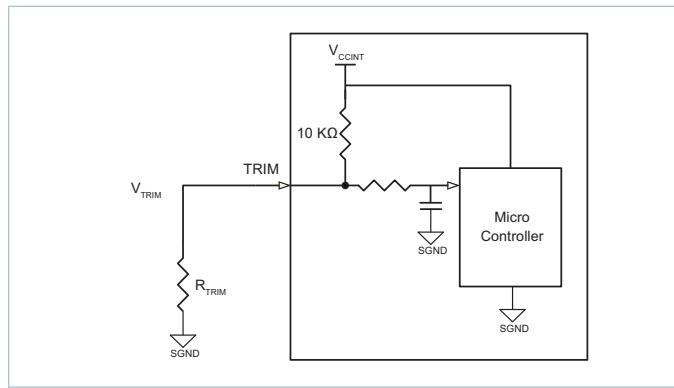


Figure 25 — TRIM Connection

The output as a function of  $V_{TRIM}$  is defined by equation (1) for  $1.00 \text{ V} \leq V_{TRIM} \leq 2.75 \text{ V}$ , and allows for an output voltage ranging from 20.0 V to 55.0 V.

The TRIM pin is pulled up internally to  $V_{CC\_INT}$  thorough a 10 kΩ resistor.  $V_{TRIM}$  can be actively set with a DAC that is ground referenced to SGND.  $V_{TRIM}$  can be passively set by connecting a resistor,  $R_{TRIM}$ , from TRIM to SGND such that the voltage divider made with  $V_{CC\_INT}$  and the 10 kΩ pull up yields the desired  $V_{TRIM}$ . The formula for calculating this resistor is provided in Equation (1a).

$$V_{OUT} = V_{TRIM} \cdot 20 \quad (1)$$

$$R_{TRIM} = \frac{10 \text{ k}\Omega \cdot V_{TRIM}}{V_{CC\_INT} - V_{TRIM}} = \frac{10 \text{ k}\Omega \cdot V_{OUT\_SET}}{20 \cdot V_{CC\_INT} - V_{OUT\_SET}} \quad (1a)$$

For  $1.00 \text{ V} \leq V_{TRIM} \leq 2.75 \text{ V}$  where  $V_{OUT\_SET}$  is the desired output voltage.

The output voltage transfer function saturates for applied TRIM voltages above approximately 2.75 V as illustrated in Figure 26 to prevent the output from being driven above its rated output voltage.

When TRIM is set lower than 1.00 V the output voltage is not specified and stable operation is not guaranteed.

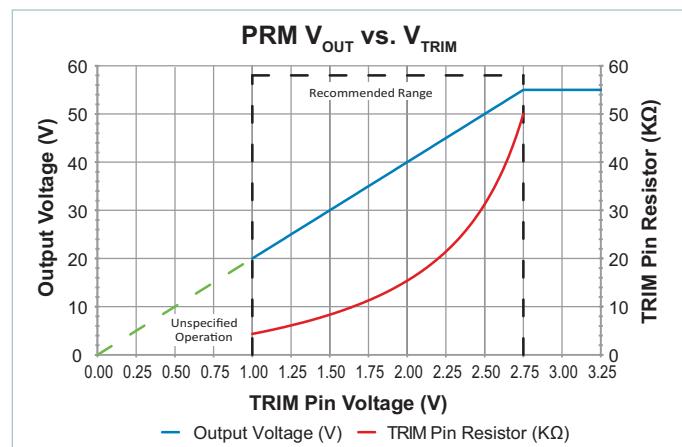


Figure 26 — PRM  $V_{OUT}$  vs.  $V_{TRIM}$

When trim is enabled the voltage at this pin is sampled at 120  $\mu\text{s}$  intervals to determine the trim level. The output can be dynamically trimmed during normal operation, however it is not recommended to use this pin in an external analog feedback loop.

Refer to Table 1 for a summary of the TRIM pin functionality and the recommended voltage/resistance that should be applied to this pin.

Trim Pin Function Summary				
Operating State		$V_{TRIM}$	$R_{TRIM}$	Detected and Latched
Remote Sense / Child Operation		<0.45 V	<1 kΩ	At application of $V_{IN}$ when ENABLE first transitions high
Adaptive Loop Operation		>0.55 V [2]	>3 kΩ [2]	At application of $V_{IN}$ when ENABLE first transitions high
Adaptive Loop Operation Trim Mode	Trim Active $V_{OUT} = 20 * V_{TRIM}$	1.00 V to 2.75 V	4.32 kΩ to 49.9 kΩ	At every start up when ENABLE transitions high
	Trim Inactive $V_{OUT} = 48.0 \text{ V}$	>3.20 V	>10 MΩ	

Table 1 — TRIM Pin Function Summary

[2] It is not recommended to configure TRIM with a voltage less than 1.00 V in Adaptive Loop Operation

### Adaptive Loop Compensation (Adaptive Loop Operation)

A factorized power system naturally has a DC load line associated with it since the regulator stage (PRM) is positioned before the isolation and voltage transformation stage (VTM). Consider for a moment a factorized power system that has the following parameters:

- $V_F = 40 \text{ V}$
- $K_{VTM} = 1/4$
- $R_{OUT\_VTM} = 10 \text{ mohm} @ 25^\circ\text{C}$

At no load the output voltage at the load will be equal to 10 V ( $V_F \cdot K_{VTM}$ ). With increasing load current, the output voltage at the load will drop at a rate proportional to the VTM's  $R_{OUT}$ . It should be noted that the  $R_{OUT}$  has a positive temperature coefficient and so the DC load line changes with temperature.

If the presence of this load line is acceptable for your application, then the PRM can be configured by way of the TRIM pin alone. Please refer to the Trimming the Output Voltage section for details. In this case both the AL and VT pins should be left open.

If the presence of this load line is undesirable, the load line can be eliminated by way of the PRMs Adaptive Loop (AL) engine. The AL engine measures the output current of the PRM and accordingly increases the output voltage of the PRM in order to regulate the PRMs output resistance to a fixed negative resistance,  $R_{LL\_AL}$ , settable by way of the AL pin.  $R_{LL\_AL}$  should be sized to exactly cancel the  $R_{OUT}$  of the VTM at  $25^\circ\text{C}$ . The AL engine is also able to account for the positive temperature coefficient of  $R_{OUT}$  by way of its VT pin which will be explained shortly.

### Setting the Adaptive Loop Load Line (Adaptive Loop Operation)

To determine an appropriate value for the compensation slope ( $R_{LL\_AL}$ ) it helps to reflect the VTM's output resistance to the input side of the VTM. A resistance on the output side of the VTM is scaled by the VTM's transformer ratio ( $K_{VTM}$ ) squared as defined by equation (2):

$$R_{LL\_AL} = R_{OUT\_REFL} = R_{OUT\_VTM\_25C} \cdot \left( \frac{1}{K_{VTM}} \right)^2 \quad (2)$$

Where

$R_{OUT\_VTM}$  is the VTM output resistance at  $25^\circ\text{C}$

$K_{VTM}$  is the VTM transformer ratio  $V_{IN}/V_{OUT}$

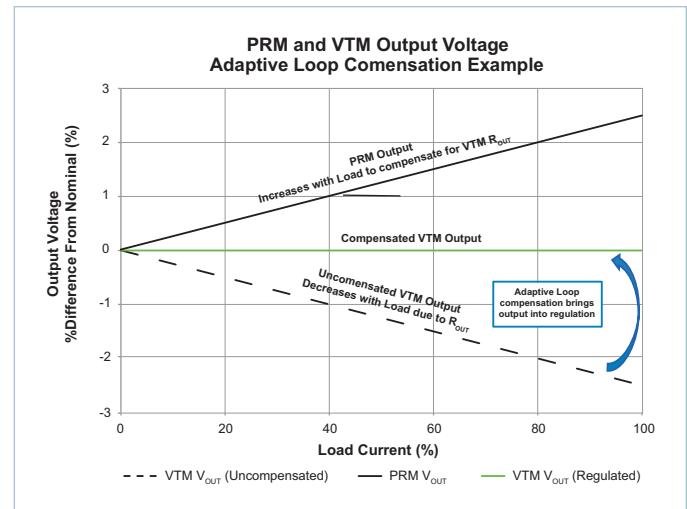


Figure 27 — Adaptive Loop Compensation Illustration

For our hypothetical VTM from above (with  $K_{VTM} = 1/4$  and  $R_{OUT\_VTM} = 10 \text{ m}\Omega$ ) the output resistance reflected over to the input would be equal to  $160 \text{ m}\Omega$ . For this example,  $R_{LL\_AL}$  should be set to  $-160 \text{ m}\Omega$  to approximately cancel at  $25^\circ\text{C}$  the inherent load line from the VTM.

$R_{LL\_AL}$  is set by the voltage difference between the AL pin and SGND pin,  $V_{AL}$  per the following formula:

$$R_{LL\_AL} = V_{AL} \cdot (-0.5) \Omega/V \quad (3)$$

$$V_{AL} \leq 3.10 \text{ V}$$

Where  $V_{AL}$  is the voltage on the AL pin

$V_{AL}$  is sampled by a 10-bit ADC, whose input is connected to  $V_{CC\_INT}$  through a  $10 \text{ k}\Omega$  pull up resistor. This pull up disables the AL engine when the AL pin is left open.  $V_{AL}$  can be actively set with a DAC that is ground referenced to SGND.  $V_{AL}$  can be passively set by connecting a resistor,  $R_{AL}$  from AL to SGND such that the voltage divider made with  $V_{CC\_INT}$  and the  $10 \text{ k}\Omega$  pull up yields the desired  $V_{AL}$ . The formula for calculating this resistor is provided in Equation (4).

$$R_{AL} = \frac{10 \text{ k}\Omega \cdot V_{AL}}{V_{CC\_INT} - V_{AL}} \quad (4)$$

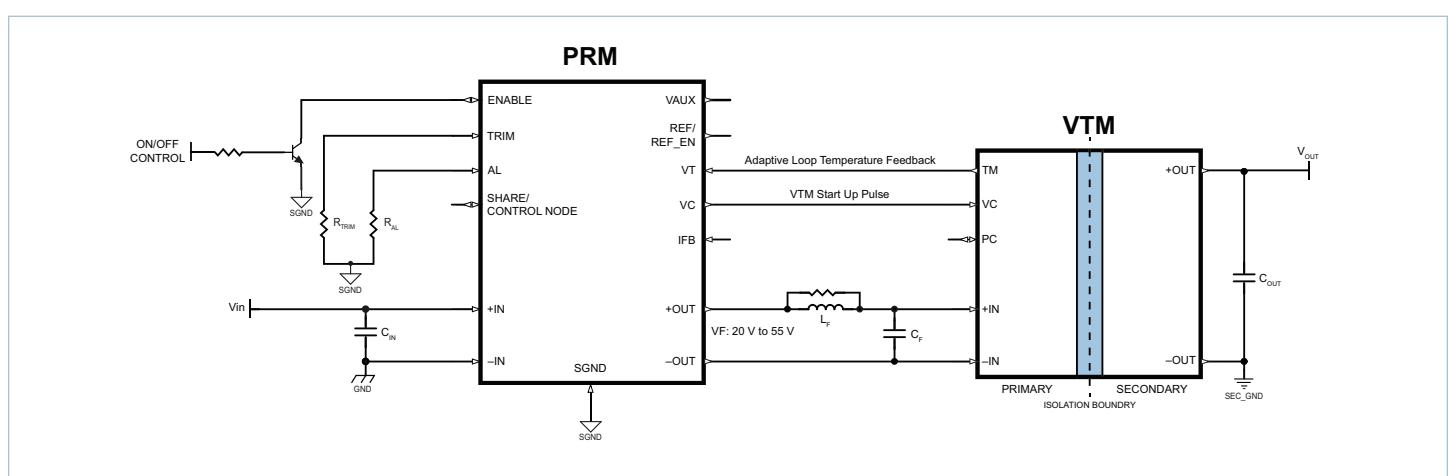
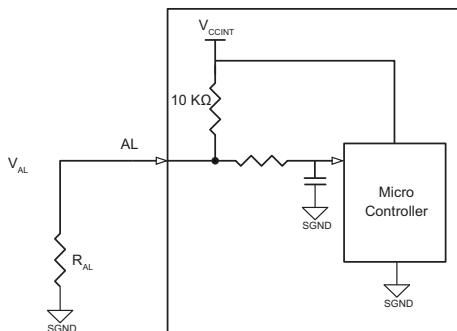


Figure 28 — PRM-VTM Adaptive Loop Example

**Figure 29** — AL Connections

Similar to TRIM, AL is sampled during every start up to determine if the Adaptive Loop load line is enabled or disabled. If the AL pin is allowed to pull up to 3.20 V or higher during start up, then the PRM will disable the Adaptive Loop load line as long as the PRM remains operating. In this case, for all subsequent operation the output voltage will remain at the set voltage, and the AL pin will be ignored.

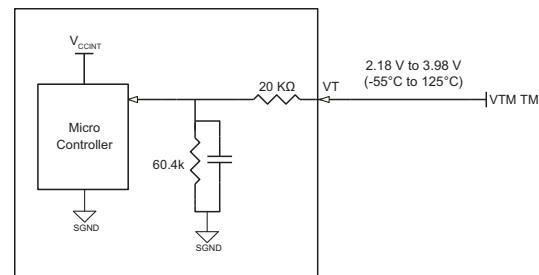
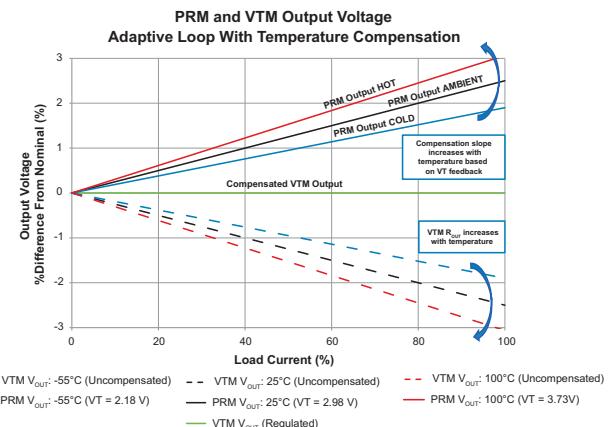
This selection persists until the PRM is restarted with the ENABLE pin, or due to fault auto-recovery. When AL is enabled, the voltage at this pin is sampled at 120  $\mu$ s intervals to determine the load line. The load line can be adjusted during normal operation, however it is not recommended to use this pin in an external analog feedback loop.

#### Adaptive Loop Temperature Compensation (Adaptive Loop Operation)

By connecting the VT pin of the PRM to the VTM's TM pin, the PRM is able to monitor the internal temperature of the VTM. Knowing the VTM's internal temperature and the temperature coefficient of the VTM's  $R_{OUT}$ , which is preprogrammed into the PRMs microcontroller, the AL engine is able to scale the nominal value of  $R_{LL\_AL}$  (set by the AL pin) to track the VTM's  $R_{OUT}$  over temperature. In this way the output resistance of the PRM can be tuned to cancel the output resistance of the VTM with the addition of a single resistor across the AL pin and a connection of the VTM's TM pin to the PRMs VT pin.

The VTM TM voltage is equal to the VTM internal sensed temperature in Kelvin divided by 100. For a temperature range of -55°C to 125°C the TM voltage will range from 2.18 V to 3.98 V. The Adaptive Loop temperature compensation is pre-programmed into the internal microcontroller and is 0.3%/°C assuming the VT pin is connected to the TM pin of a compatible VTM.

The TM pin has an internal pull down to SGND, and temperature compensation is disabled for VT voltages less than 1.9 V. To disable temperature compensation, leave the VT pin unconnected and open circuit. When disabled, the temperature defaults 25°C.

**Figure 30** — VT Connections**Figure 31** — Adaptive Loop Temperature Compensation Illustration

The discussion thus far only considered the case where the AL engine is used to compensate for the  $R_{OUT}$  of the VTM. The AL engine can be more generally used to account for distribution resistances in both the factorized bus and the VTM's output distribution bus. For more information on how to apply the AL engine towards this end please contact Vicor's Applications Engineering department.

#### Stability Considerations and External Capacitance (Adaptive Loop Operation)

In Adaptive Loop Operation, the internal voltage regulation is enabled which has a pre-determined, fixed compensation network. The compensation is designed to be stable over a fixed set of operating and load conditions including load capacitance.

Besides internal output capacitors, external output capacitors also contribute to the closed loop frequency response, thus should be identified and understood, in order to maintain the control loop stability. This includes capacitance placed directly on the PRM output, as well as capacitance on the output of any downstream VTM (if used) reflected to its input.

Figure 32 illustrates the requirements for external capacitors for both the capacitance and ESR value. As shown in Figure 32 (a), the maximum capacitance value of ceramic capacitor is 25  $\mu$ F, and the capacitance of a combination of ceramic and electrolyte capacitors needs to be less than 47  $\mu$ F. As shown in Figure 32 (b) and (c), the ESR value of electrolyte capacitors needs to be between 0.1  $\Omega$  and 1  $\Omega$ ; the ESR value of ceramic capacitors needs to be between 2 m $\Omega$  and 200 m $\Omega$ .

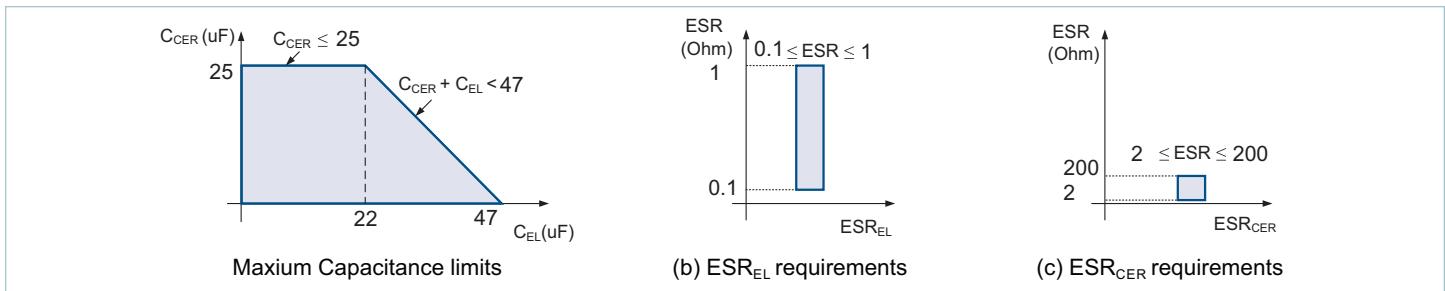


Figure 32 — Output Capacitance Limits

**Current Limit (Adaptive Loop Operation)**

In Adaptive Loop Operation, the current limit is controlled by the internal microcontroller. The current limit approximates a “brick-wall” limit where the output current is prevented from crossing the current limit threshold by reducing the output voltage. The current limit threshold is pre-programmed into the internal microcontroller and cannot be changed externally.

When the internal sensed current crosses the current limit threshold, the current limit will be activated after the detection time  $t_{LIM\_SUPV}$ . Once activated, the microcontroller will reduce the error amplifier reference voltage(represented by REF) in order to maintain the output current at the limit value. Current limit is able to reduce the output down to  $V_{OUT\_UVP}$ , below which the device will shut down do to output under voltage protection.

**Soft Start Timing and Start up (Adaptive Loop Operation)**

In Adaptive Loop Operation, the PRM has an internal soft start sequence which is initiated at every start up. This allows the PRM to start into fully discharged load capacitance. The soft start sequence ramps the output by modulating the error amplifier reference voltage (REF). The result is that the PRM output will rise at a controlled rate until the final voltage setpoint is reached. The total ramp time is typically 1.8 ms independent of the output trim level. This soft start ramp time is preprogrammed into the microcontroller and cannot be changed externally.

**Load Transient Response (Adaptive Loop Operation)**

In Adaptive Loop Operation, response time is dependent on the internal compensation. When the Adaptive Loop load line is disabled, the PRM output voltage will recover to the initial set value as illustrated in Figure 33 and Figure 34.

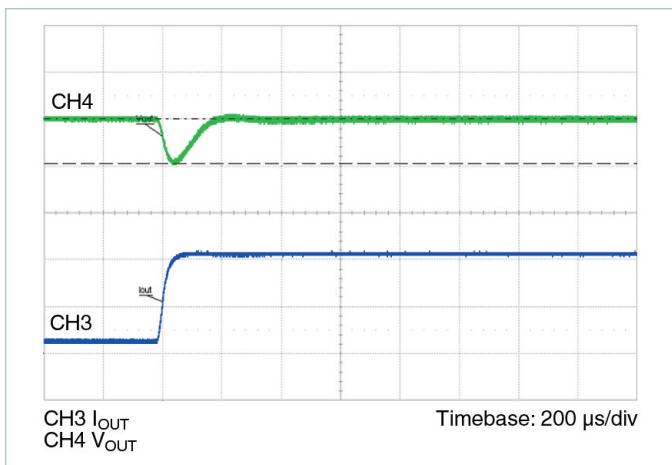


Figure 33 — PRM Example 10% to 100% Load Transient Response, Adaptive Loop Load Line Disabled

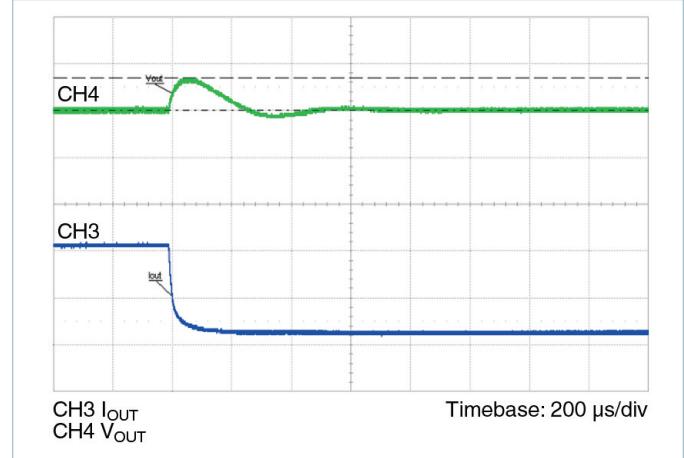
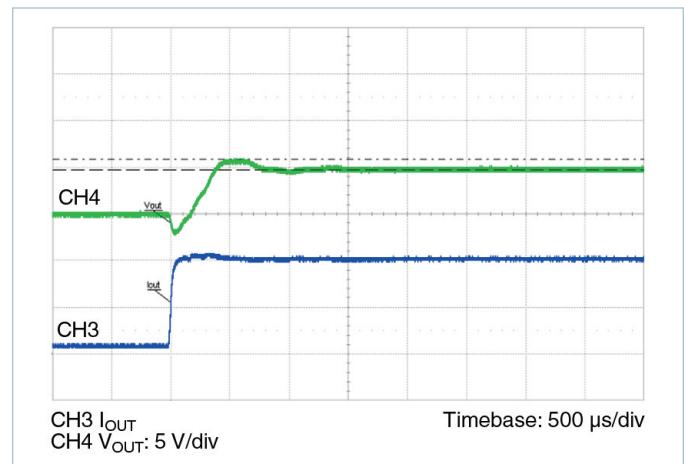


Figure 34 — PRM Example 100% to 10% Load Transient Response, Adaptive Loop Load Line Disabled

When the Adaptive Loop load line is enabled, the voltage will recover to the value determined by the set point and Adaptive Loop load line settings as illustrated in Figure 35.

Figure 35 — PRM Example 10% to 100% Load Transient Response, Adaptive Loop Load Line Enabled,  $V_{AL} = 0.96$  V

Actual response times are model dependent and will change based on the load step magnitude, load capacitance and operating conditions.

Because the compensation is fixed internally the load transient response cannot be altered for Adaptive Loop Operation. In order to improve the load transient response performance, the part can be configured for Remote Sense Operation with an external voltage control loop optimized for the specific intended operating conditions. Remote Sense Operation is described in the next section.

### Arrays (Adaptive Loop Operation)

In Adaptive Loop operation a parent-child configuration is used for arrays. Up to 5 PRMs of the same type may be placed in parallel to expand the power capacity of the system.

One PRM is designated as the parent and contains the active control loop which considers control pin inputs and drives SHARE. The other PRMs listen to SHARE and act as child powertrains only. The following high-level guidelines must be followed in order for the resultant system to start up and operate properly, and to avoid overstress or exceeding any absolute maximum ratings.

- One PRM must be designated as a parent through configuring the TRIM pin voltage within the recommended range.
- All other PRMs must be designated as child PRMs by tying TRIM pins to SGND. It is recommended to make this connection through a  $0\ \Omega$  jumper for troubleshooting purposes.
- All PRMs in the array must be powered from a common power source so that the input voltage to each PRM is the same. The IN pins of all PRMs must be connected together.
- An independent fuse for each PRM +IN connection is required to maintain safety certifications (see Fusing section).
- An independent inductor for each PRM +IN connection is recommended when used in an array, to control circulating currents among the PRM inputs and reduce the impact of beat frequencies.
- Mismatches in both inductance, and resistance from the common power source to each PRM should be minimized.
- ENABLE pins must be connected together for start up synchronization and proper fault response of the array.

- SHARE pins must be connected together to enable sharing. The bandwidth requirements of SHARE are low enough that the bus can be considered a lumped element, rather than a transmission line, and so star connections to the parent PRM with stubs, as well as daisy chain connections are permitted.
- The resistances between child unit SHARE pins and the parent's should be well matched, to avoid introducing additional sharing mismatches. The SHARE bus should not be routed under any PRM. SHARE bus parasitic capacitance to +IN or +OUT should be minimized.
- SGND of the parent PRM is the reference for all control loop functions. The SGND pins of each child PRMs should be connected to the SGND reference node on the board through a  $1\ \Omega$  resistor.
- When operating within an array, the parent PRM is rated for full power while the child PRMs are de-rated to the array rated power and current values provided for Child Operation ( $P_{OUT\_ARRAY}, I_{OUT\_ARRAY}$ ). The number of PRMs required to achieve a given array capacity must consider these de-ratings to avoid overstressing any PRM in the array.
- Adaptive Loop design procedures above will hold for an array, in general, although some parameters must be scaled against the number of PRMs in the system.

Arrays of more than 5 PRMs may be possible through use of external circuitry. Please contact Vicor Applications for assistance with array sizing above 5 units.

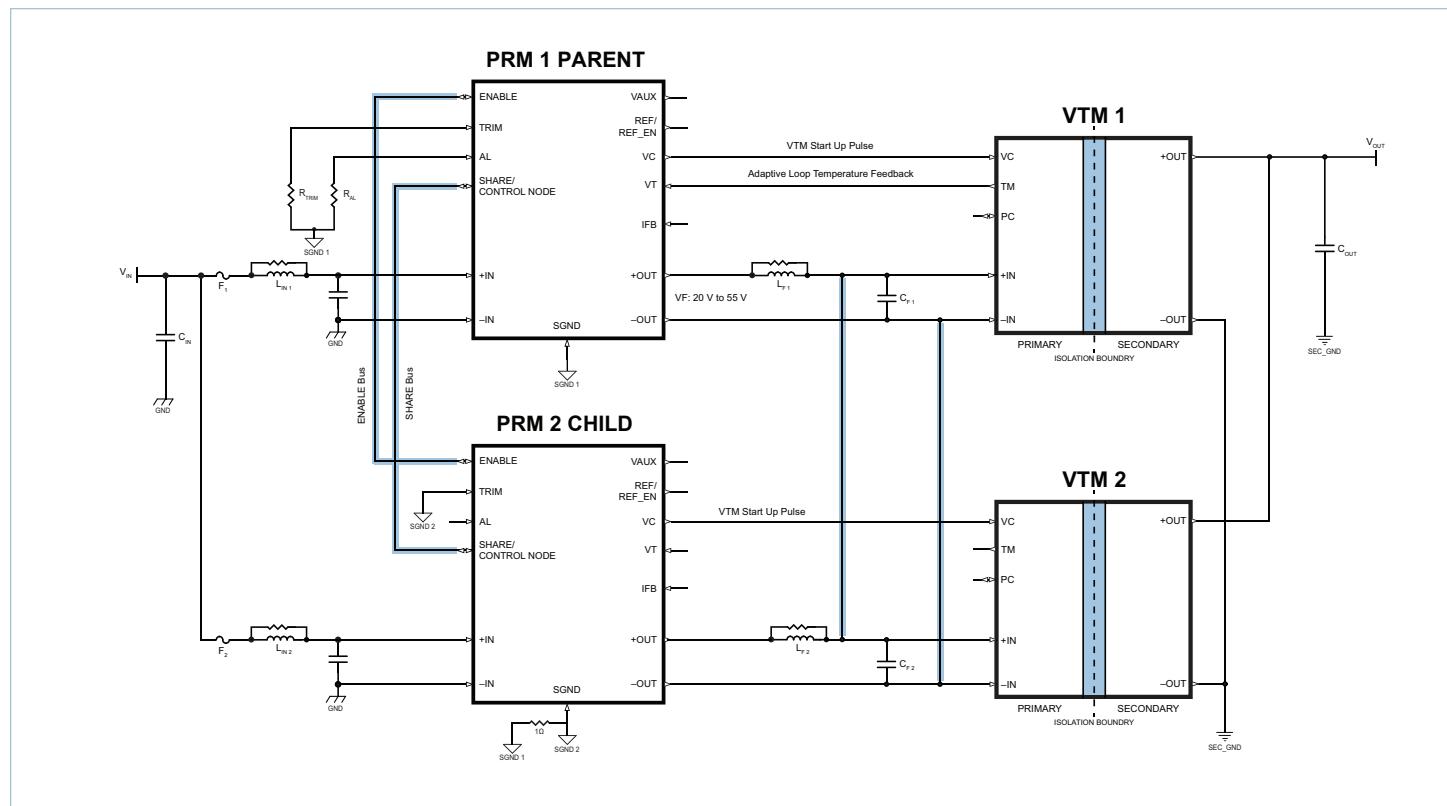


Figure 36 — Adaptive Loop Array Example

## Design Guidelines (Remote Sense Operation)

In Remote Sense Operation, the PRM48By480x500A00 is an intelligent powertrain module designed to fully exploit external output voltage feedback and current sensing sub-circuits. These two external circuits are illustrated in Figure 36, which shows an example of the PRM in a standalone application with local voltage feedback and high side current sensing.

In general, these circuits include a precision voltage reference, an operational amplifier which provides closed loop feedback compensation, and a high side current sense circuit which includes a shunt and current sense IC.

The following design procedures refer to the circuit shown in Figure 36.

### Setting the Output Voltage Level (Remote Sense Operation)

The output voltage setpoint is a function of the voltage reference and the output voltage sense ratio. With reference to Figure 36, R1 and R2 form the output voltage sensing divider which provides the scaled output voltage to the negative input of the error amplifier; a dedicated reference IC provides the reference voltage to the positive input of the error amplifier. Under normal operation, the error amplifier will keep the voltages at the inverting and non-inverting inputs equal, and therefore the output voltage is defined by:

$$V_{OUT} = V_{REF} \cdot \frac{R1 + R2}{R2} \quad (5)$$

Note that the component R1 will also factor into the compensation as described in a later section.

It is important to apply proper slew rate to the reference voltage rise when the control loop is initially enabled. The recommended range for reference rise time is 1 ms to 9 ms. The lower rise time limit will ensure optimized modulator timing performance during start up, and to allow the current limit feature (through IFB pin) to fully protect the device during power-up. The upper rise time limit is needed to guarantee a sufficient factorized bus voltage is provided to any downstream VTM input before the end of the VC pulse.

### Setting the Output Current Limit and Overcurrent Protection Level (Remote Sense Operation)

In Remote Sense Operation, the internal current sensing is disabled, and an external current sense amplifier must be implemented to provide feedback to the IFB pin.

The current limit and overcurrent protection set points are linked, and scale together against the current sense shunt, and the gain of the current sense amplifier. The output of the current sense IC provides the IFB voltage which has  $V_{IFB\_IL}$  and  $V_{IFB\_OC}$  thresholds for the two functions respectively. The set points are therefore defined by:

$$I_{IL} = \frac{V_{IFB\_IL}}{R_s \cdot G_{CS}} \quad (6)$$

and

$$I_{OC} = \frac{V_{IFB\_OC}}{R_s \cdot G_{CS}} \quad (7)$$

where  $G_{CS}$  is the gain of the current sense amplifier.

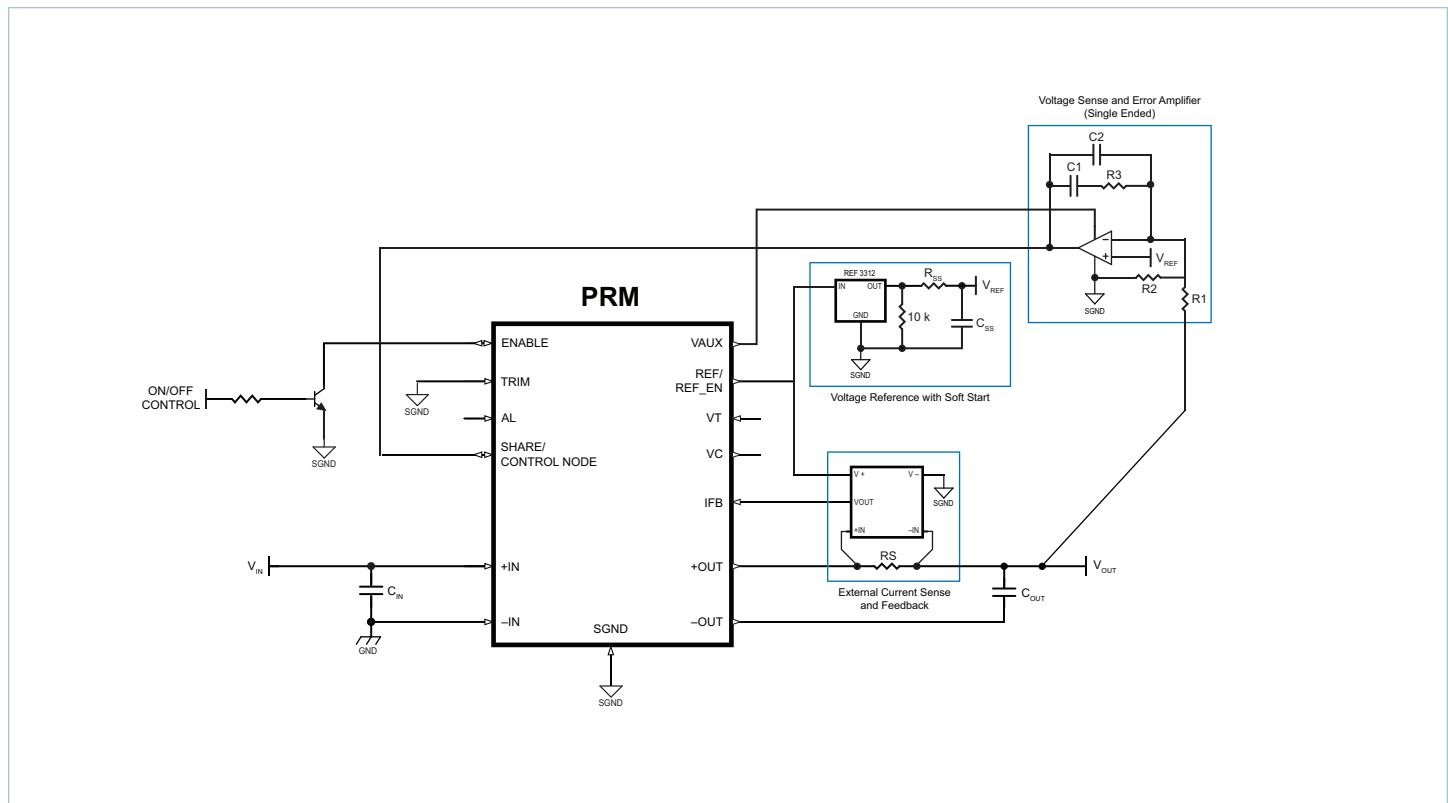


Figure 37 — Remote Sense Example



**Midband Gain Design: R1, R3 (Remote Sense Operation)**

With reference to Figure 37: curve ABC is the:

- minimum output voltage in the application
- maximum input voltage expected in the application
- maximum load

PRM open loop response, and is where the maximum crossover frequency occurs. In order for the maximum crossover frequency to occur at the design choice  $F_{CMAX}$ , the compensation gain must be equal and opposite of the powertrain gain at this frequency. For stability purposes, the compensation should be in the Mid-band (J-K) at the crossover. Using Equation (8), the mid-band gain can be selected appropriately.

**Compensation Zero Design :C1 (Remote Sense Operation)**

With reference to Figure 37: curve EFG is the:

- maximum output voltage in the application
- minimum input voltage expected in the application
- minimum load in the application

PRM open loop response, and is where the minimum crossover frequency  $F_{CMIN}$  occurs. Based on stability criteria, the compensation must be in the mid-band at the minimum crossover frequency, therefore  $F_{CMIN}$  will occur where EFG is equal and opposite of  $G_{MB}$ . C1 can be selected using Equation (9) so that  $F_{Z1}$  occurs prior to  $F_{CMIN}$ .

**High Frequency Pole Design: C2 (Remote Sense Operation):**

Using Equation (10), C2 should be selected so that  $F_{P2}$  is at least one decade above  $F_{CMAX}$  and prior to the gain bandwidth product of the operational amplifier (10MHz for this example). For applications with a higher desired crossover frequency the use of a high gain bandwidth product amplifier may be necessary to ensure that the real pole can be set at least one decade above the maximum crossover frequency.

### Arrays (Remote Sense Operation)

In Remote Sense Operation up to 10 PRMs of the same type may be placed in parallel to expand the power capacity of the system. All PRMs within the array are configured for Remote Sense Operation and are driven by an external control circuit which considers the control inputs and drives the CONTROL NODE bus. The following high-level guidelines must be followed in order for the resultant system to start up and operate properly, and to avoid overstress or exceeding any absolute maximum ratings.

- All PRMs must be configured for Remote Sense Operation by tying TRIM pins to SGND. It is recommended to make this connection through a  $0\ \Omega$  jumper for troubleshooting purposes.
- All PRMs in the array must be powered from a common power source so that the input voltage to each PRM is the same.
- An independent fuse for each PRM +IN connection is required to maintain safety certifications (see Fusing section).
- An independent inductor for each PRM +IN connection is recommended when used in an array, to control circulating currents among the PRM inputs and reduce the impact of beat frequencies.
- Mismatches in both inductance, and resistance from the common power source to each PRM should be minimized.
- ENABLE pins must be connected together for start up synchronization and proper fault response of the array.
- Reference supply to the control loop voltage reference and current sense circuitry must be enabled when all modules' R<sub>EF\_EN</sub> pins have reached their operational voltage levels.
- A single external control circuit must be implemented as

described in the Remote Sense Operation design guidelines. The control circuit should drive the CONTROL NODE bus.

- CONTROL NODE pins must be connected together to enable sharing. The bandwidth requirements of CONTROL NODE are low enough that the bus can be considered a lumped element, rather than a transmission line, and so star connections as well as daisy chain connections are permitted.
- Each PRM must have its own local current shunt and current sense circuitry to drive its IFB pin.
- The resistances between CONTROL NODE pins should be well matched, to avoid introducing additional sharing mismatches. The CONTROL NODE bus should not be routed under any PRM. Parasitic capacitance to +IN or +OUT should be minimized.
- One PRM should be designated to provide the SGND reference, VAUX, and REF\_EN voltages for the external circuitry.
- The SGND pins of each PRM should be connected to the SGND reference node on the board through a  $1\ \Omega$  resistor.
- When operating within an array, the PRMs are de-rated to the array rated power and current values provided for Remote Sense Operation ( $P_{OUT\_ARRAY}$ ,  $I_{OUT\_ARRAY}$ ). The number of PRMs required to achieve a given array capacity must consider these de-ratings to avoid overstressing any PRM in the array.
- When using VAUX to power external circuitry, total current draw including CONTROL NODE sink currents must be taken into account to ensure the maximum VAUX current is not exceeded. Arrays of more than 5 PRMs may require additional circuitry to provide the required source current. Contact Vicor Applications Engineering for more information.

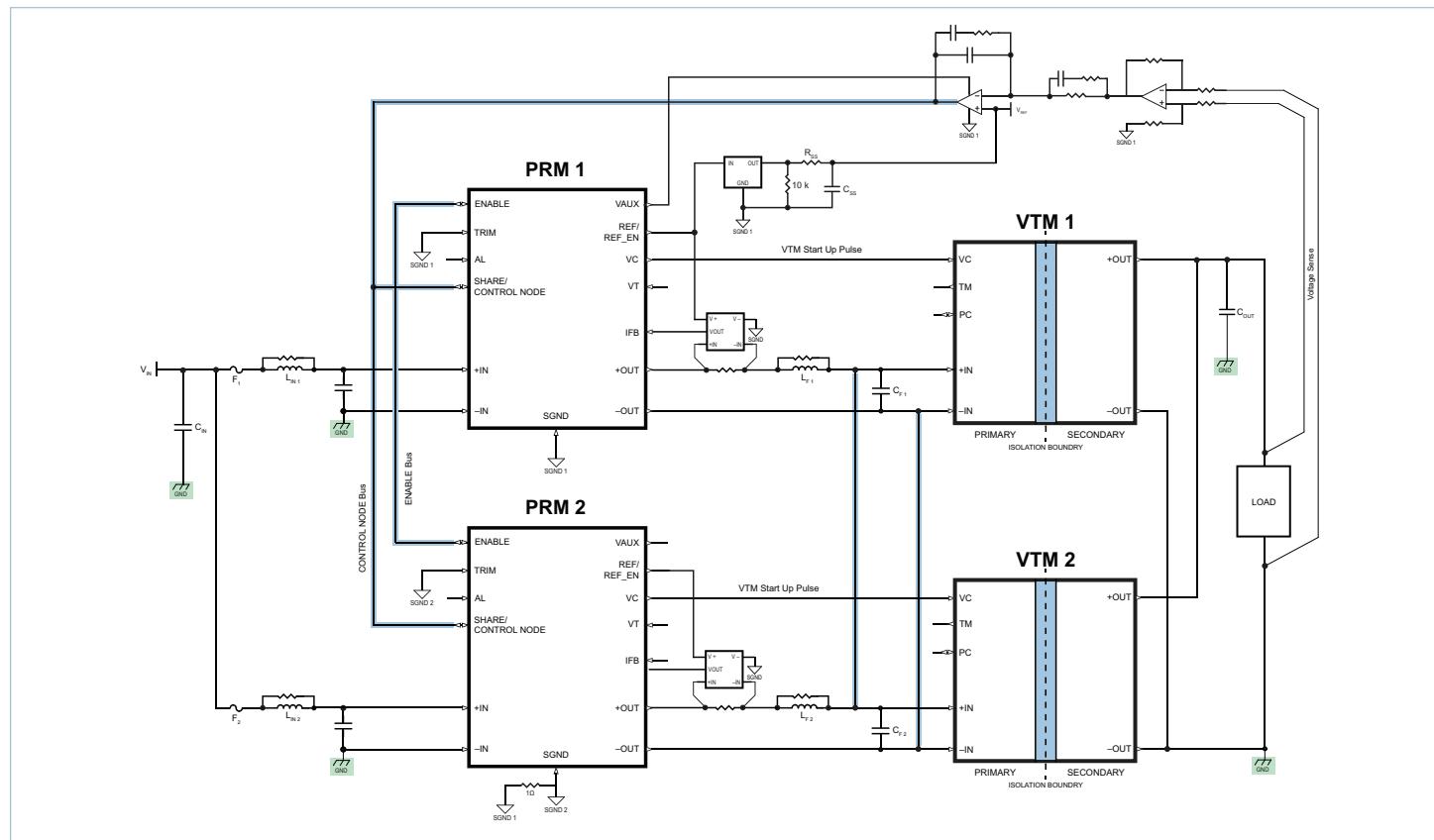


Figure 39 — Non-Isolated Remote Sense Array Example

[1] Non-Isolated Configuration: –Out connected to -IN



### **Input Filter Stability**

The PRM can provide very high dynamic transients. It is therefore very important to verify that the voltage supply source as well as the interconnecting lines are stable and do not oscillate. For this purpose, the converter dynamic input impedance magnitude  $|r_{EQ\_IN}|$  is provided in Figures 21, 22, 23. It is recommended to provide adequate design margin with respect to the stability conditions illustrated in the previous sections.

### **Inductive source and local, external input decoupling capacitance with negligible ESR (i.e.: ceramic type)**

The voltage source impedance can be modeled as a series  $R_{LINE}$   $L_{LINE}$  circuit. The high performance ceramic decoupling capacitors will not significantly damp the network because of their low ESR; therefore in order to guarantee stability the following conditions must be verified:

$$R_{line} > \frac{L_{line}}{(C_{IN\_INT} + C_{IN\_EXT}) \cdot |r_{EQ\_IN}|} \quad (13)$$

$$R_{line} \ll |r_{EQ\_IN}| \quad (14)$$

It is critical that the line source impedance be at least an octave lower than the converter's dynamic input resistance, 14. However,  $R_{LINE}$  cannot be made arbitrarily low otherwise equation 13 is violated and the system will show instability, due to under-damped RLC input network.

### **Inductive source and local, external input decoupling capacitance with significant $R_{CIN\_EXT}$ ESR (i.e.: electrolytic type)**

In order to simplify the analysis in this case, the voltage source impedance can be modeled as a simple inductor  $L_{line}$ . Notice that the high performance ceramic capacitors  $C_{IN\_INT}$  within the PRM, should be included in the external electrolytic capacitance value for this purpose. The stability criteria will be:

$$|r_{EQ\_IN}| > R_{C_{IN\_EXT}} \quad (15)$$

$$\frac{L_{line}}{C_{IN\_EXT} \cdot R_{C_{IN\_EXT}}} < |r_{EQ\_IN}| \quad (16)$$

Equation 16 shows that if the aggregate ESR is too small – for example by using very high quality input capacitors ( $C_{IN\_EXT}$ ) – the system will be under-damped and may even become destabilized. Again, an octave of design margin in satisfying 15 should be considered the minimum.

### **Layout Considerations**

Application Note AN:005 details board layout recommendations using VI Chip® components, with details on good power connections, reducing EMI, and shielding of control signals and techniques to reference them to SGND.

Avoid routing control signals (ENABLE, TRIM, AL etc.) directly underneath the PRM. It is critical that all control signals (aside from VC and VT) are referenced to SGND, both for routing and for pull-down and bypassing purposes. VC and VT provide control and feedback from a VTM, and must be referenced to -OUT of the PRM (-IN of the VTM).

SGND is connected to -IN internally to the PRM. SGND should not be tied to any other ground in the system.

### **Input Fuse Recommendations**

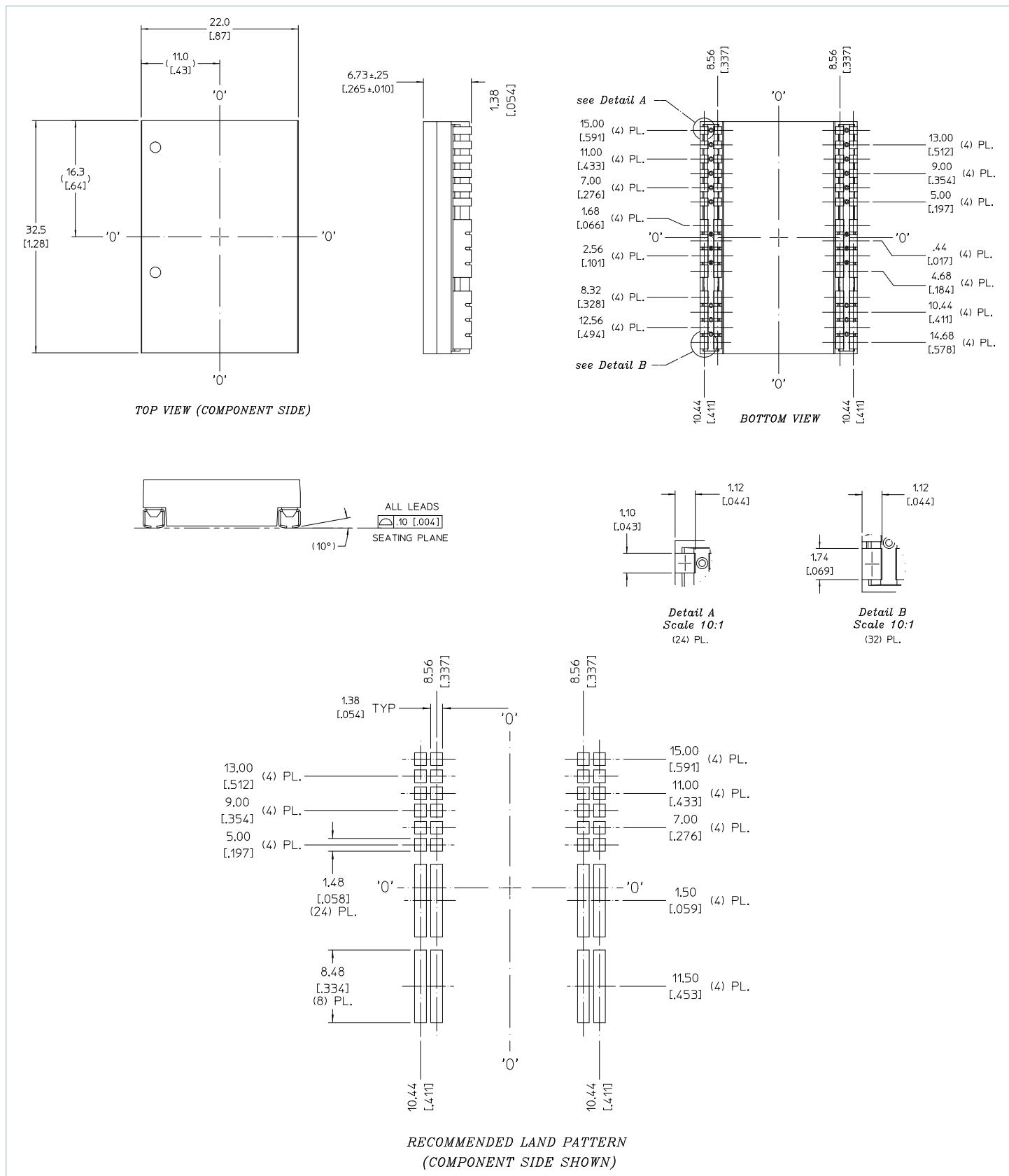
A fuse should be incorporated at the input to each PRM, in series with the +IN pin. A 20 A or smaller input fuse (Littelfuse® NANO2® 456 Series) is required to safety agency conditions of acceptability. Always ascertain and observe the safety, regulatory, or other agency specifications that apply to your specific application.

### **Thermal Considerations**

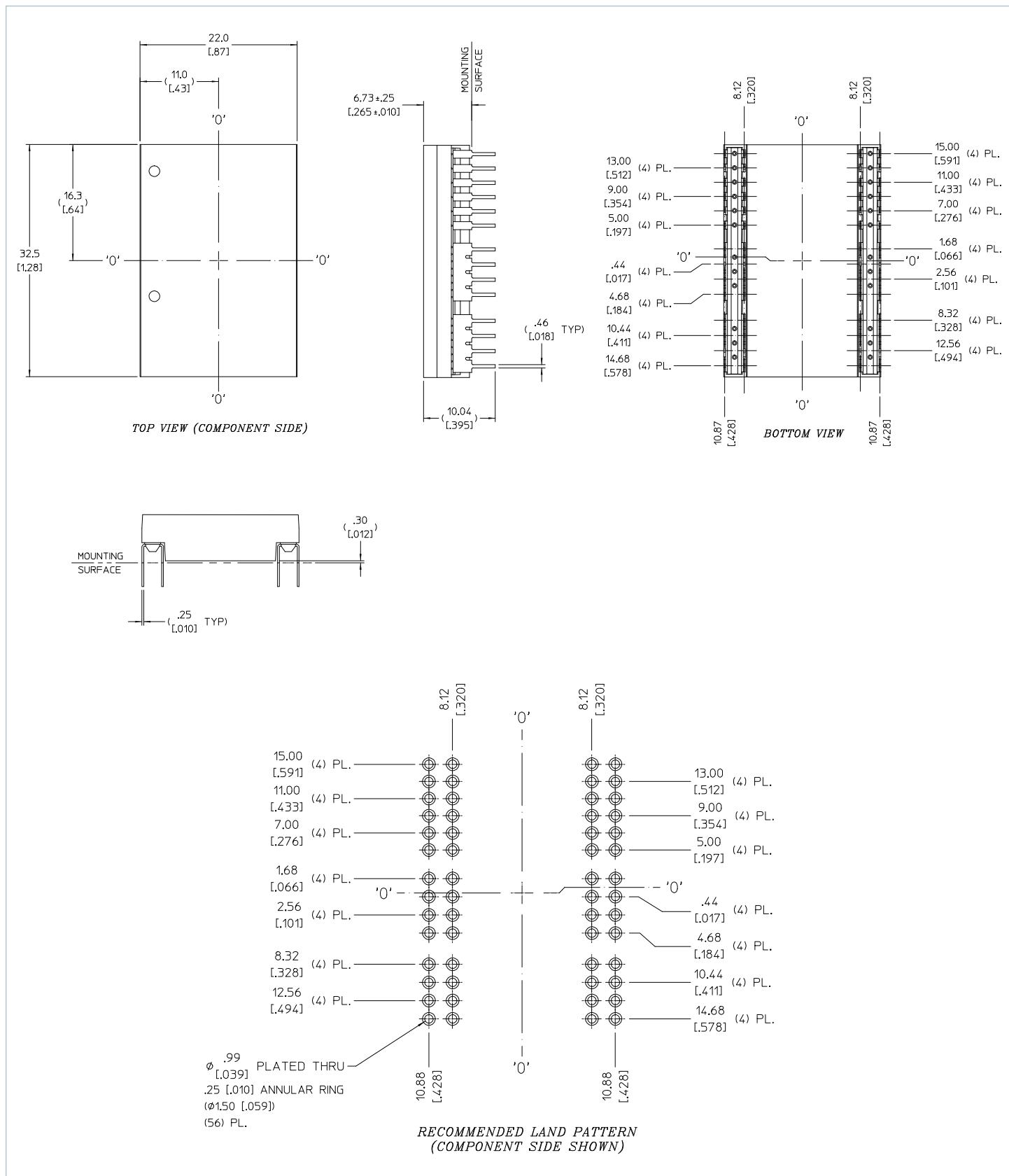
VIChip products are multi-chip modules whose temperature distribution varies greatly for each part number as well as with the input / output conditions, thermal management and environmental conditions. Maintaining the top of the PRM48By480x500A00 case to less than 100°C will keep all junctions within the VI Chip module below 125°C for most applications. The percent of total heat dissipated through the top surface versus through the J-lead is entirely dependent on the particular mechanical and thermal environment. The heat dissipated through the top surface is typically 60%. The heat dissipated through the J-lead onto the PCB board surface is typically 40%. Use 100% top surface dissipation when designing for a conservative cooling solution.

It is not recommended to use a VI Chip module for an extended period of time at full load without proper heat sinking.

## Product Outline Drawing and Recommended Land Pattern - SMD (F)



## Product Outline Drawing and Recommended Land Pattern - Through Hole (T)



## Revision History

Revision	Date	Description	Page Number(s)
1.0	11/12/12	Final approved data sheet for intital release	n/a
1.1	02/15/13	Updated format throughout	all
1.2	07/25/13	Updated Maximum Time Above 217°C Added Array Diagrams	26 34 & 38
1.3	09/30/15	Updated MSL Rating	27
1.4	11/18/15	Corrections to schematic labels	17
1.5	11/30/20	Updated terminology	1, 4, 6, 7, 8, 11, 15, 28, 29, 30, 34

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